

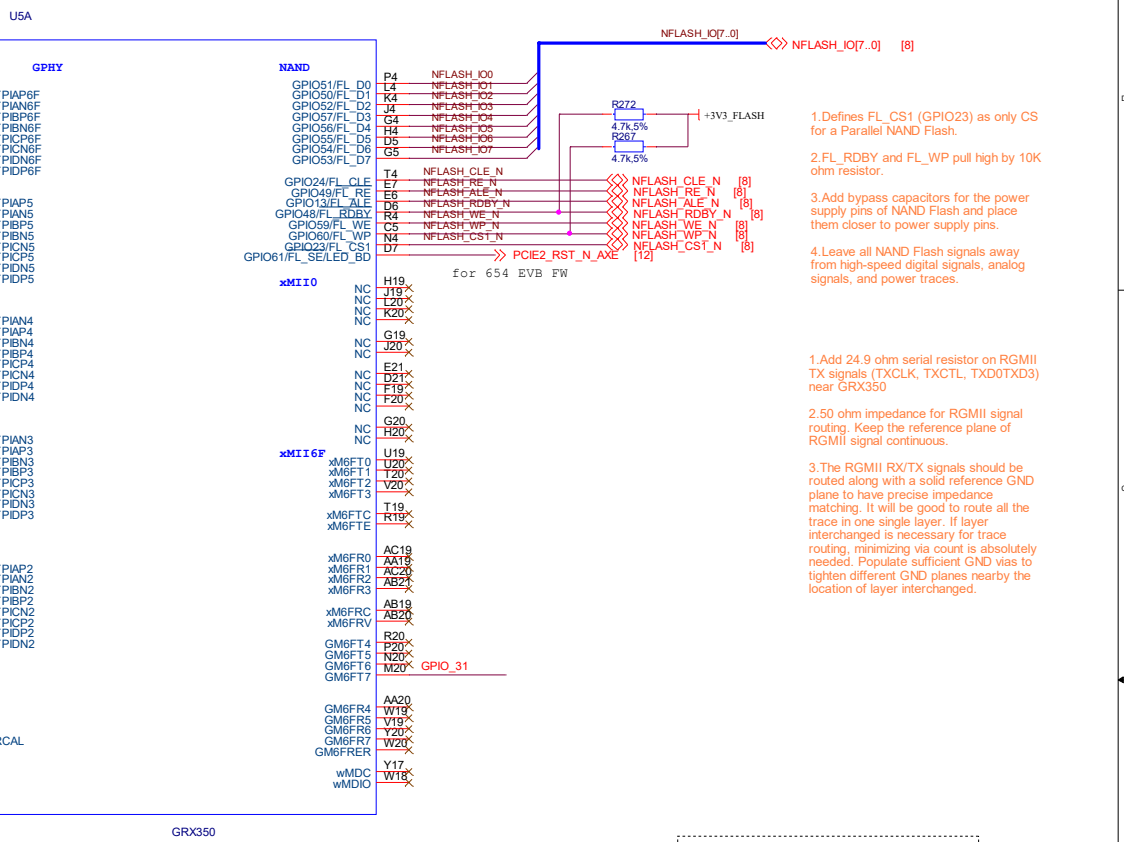
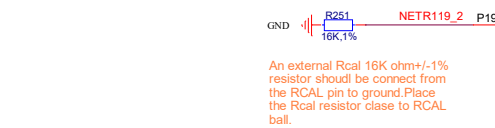
USA

GPHY			
11	GTP4 AP	GTP4_AP	AC22
11	GTP4 AN	GTP4_AN	AB23
11	GTP4 BP	GTP4_BP	AB23
11	GTP4 BN	GTP4_BN	AA21
11	GTP4 CP	GTP4_CN	AA22
11	GTP4 CN	GTP4_CN	Y21
11	GTP4 DN	GTP4_DN	Y23
11	GTP4 DP	GTP4_DP	Y22
11	GTP3 AP	GTP3_AP	W21
11	GTP3 AN	GTP3_AN	W23
11	GTP3 BP	GTP3_BP	W22
11	GTP3 BN	GTP3_BN	U22
11	GTP3 CP	GTP3_CN	U21
11	GTP3 CN	GTP3_CN	U22
11	GTP3 DN	GTP3_DN	U23
11	GTP3 DP	GTP3_DP	U23
11	GTP2 AN	GTP2_AN	R21
11	GTP2 AP	GTP2_AP	T23
11	GTP2 BN	GTP2_BP	R22
11	GTP2 BP	GTP2_CP	P22
11	GTP2 CP	GTP2_CN	P23
11	GTP2 CN	GTP2_DP	N22
11	GTP2 DP	GTP2_DN	N23
11	GTP2 DN	GTP2_DN	N23
11	GTP1 AN	GTP1_AN	M22
11	GTP1 AP	GTP1_AP	M21
11	GTP1 BN	GTP1_BP	L21
11	GTP1 BP	GTP1_CP	L21
11	GTP1 CP	GTP1_CN	K21
11	GTP1 CN	GTP1_DN	K22
11	GTP1 DN	GTP1_DP	K23
11	GTP1 DP	GTP1_DP	K23
11	GTP0 AP	GTP0_AP	J22
11	GTP0 AN	GTP0_AN	H22
11	GTP0 BN	GTP0_BP	H21
11	GTP0 BP	GTP0_CN	H23
11	GTP0 CN	GTP0_CN	G22
11	GTP0 CP	GTP0_CP	G23
11	GTP0 DN	GTP0_DP	F22
11	GTP0 DP	GTP0_DP	F21
11	GTP0 DN	GTP0_DN	F21

1.100 ohm characteristic impedance control for TPI differential signal routing. Keep the reference plane of signal continuous.

2.The TPI signals should be routed along with a solid reference GND plane to have precise impedance matching. It will be good to route all the trace in one single layer. If layer interchanged is necessary for trace routing, minimizing via count is absolutely needed. Populate sufficient GND vias to tighten different GND planes nearby the location of layer interchanged.

RCAL			
11	GTP0 AP	GTP0_AP	J22
11	GTP0 AN	GTP0_AN	H22
11	GTP0 BN	GTP0_BP	H21
11	GTP0 BP	GTP0_CN	H23
11	GTP0 CN	GTP0_CN	G22
11	GTP0 CP	GTP0_CP	G23
11	GTP0 DN	GTP0_DP	F22
11	GTP0 DP	GTP0_DP	F21
11	GTP0 DN	GTP0_DN	F21

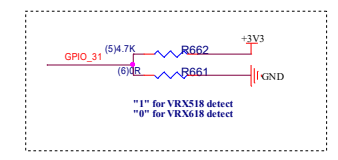


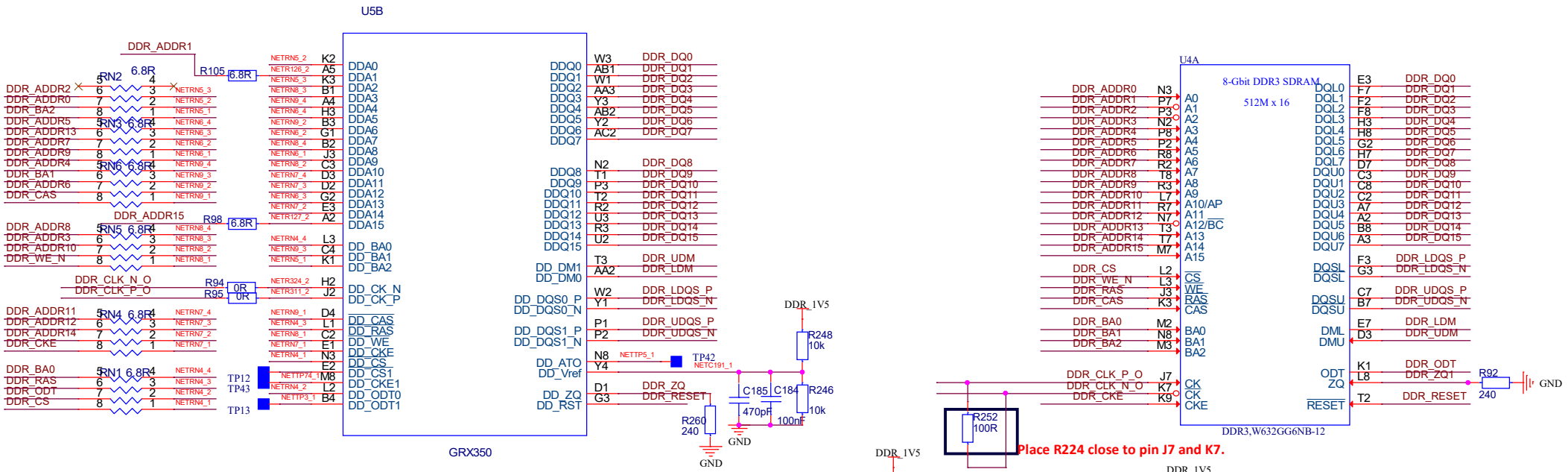
1. Defines FL_CS1 (GPIO23) as only CS for a Parallel NAND Flash.
2. FL_RDBY and FL_WP pull high by 10K ohm resistor.
3. Add bypass capacitors for the power supply pins of NAND Flash and place them closer to power supply pins.
4. Leave all NAND Flash signals away from high-speed digital signals, analog signals, and power traces.

1. Add 24.9 ohm serial resistor on RGMII TX signals (TXCLK, TXCTL, TXD0TXD3) near GRX350

2. 50 ohm impedance for RGMII signal routing. Keep the reference plane of RGMII signal continuous.

3. The RGMII RX/TX signals should be routed along with a solid reference GND plane to have precise impedance matching. It will be good to route all the trace in one single layer. If layer interchanged is necessary for trace routing, minimizing via count is absolutely needed. Populate sufficient GND vias to tighten different GND planes nearby the location of layer interchanged.

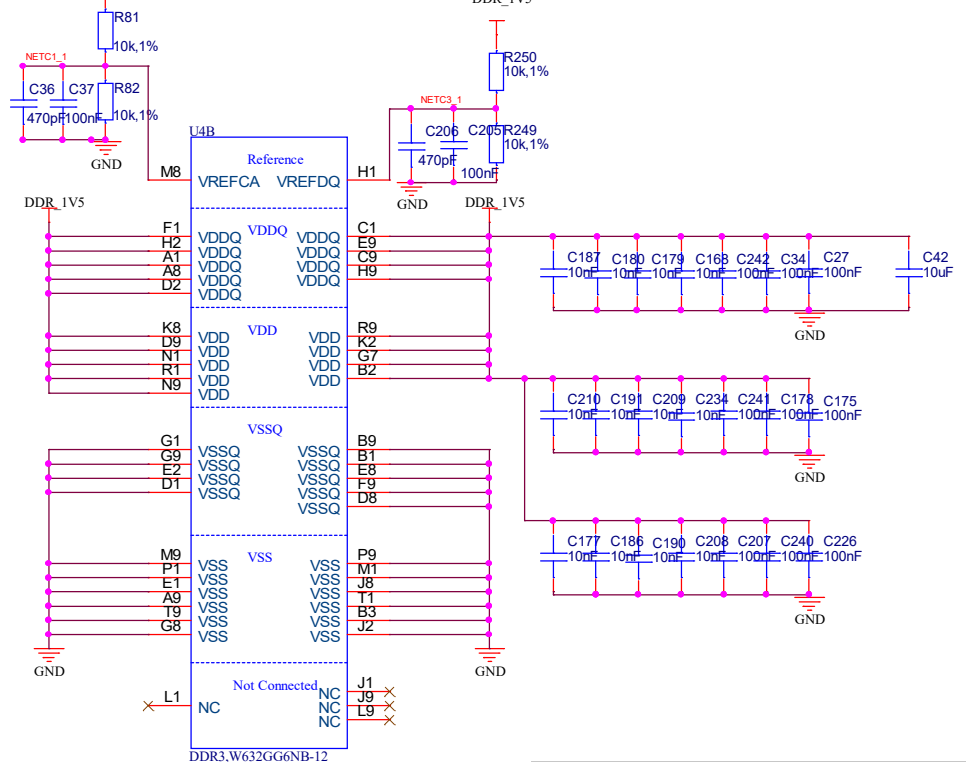


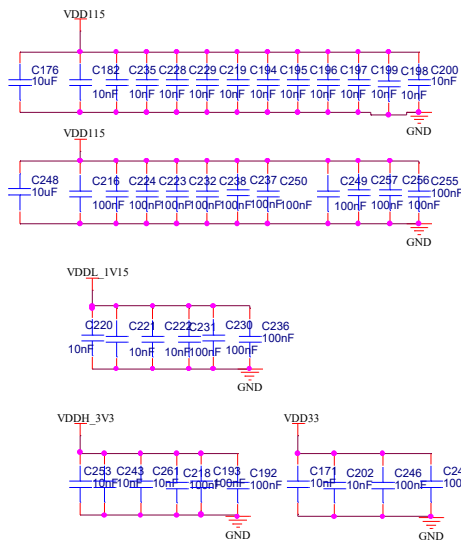


Qualified DDR3 List

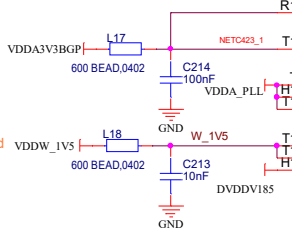
- Etron: EM6GC16EWXD-10H (64Mx16bit, single rank (CS0))
- Micron: MT41K128M16JT-125:K (128Mx16bit, single rank (CS0))
- Micron: MT41K256M16HA-125 IT:E (256Mx16bit, single rank (CS0))
- Wimbond: W634GG6LB-12 (256Mx16bit, single rank (CS0))
- Etron: EM6GE16EWCX-10H (256Mx16bit, single rank (CS0))
- Nanya: NT5CB256M16DP-EK (256Mx16bit, single rank (CS0))
- Micron: MT41K512M16HA-125:A (512Mx16bit, single rank (CS0))

1. Place 6.8ohm series termination resistors close to GRX350 for CA group.
2. An external RZQ 240 ohm +/-1% resistor should be connect from the ZQ pin to ground on both GRX350 and DDR device.
3. System DD_Vref and DDR device VREFCA and VREFDQ are separated, divided by 10K ohm +/-1% resistors.
4. 55 ohm Single-End and 100 ohm Differential signals impedance control
5. 5mils Single-End trace width, trace to trace clearance is 10mils
6. Length Matching
 Maximum trace length difference (skew) between DQS and DQS#: ± 4 mils (< 0.6 ps).
 Maximum trace length difference (skew) DQ to DQS/ DQS# domain: ± 30 mils (< 10 ps).
 Maximum trace length difference (skew) Addr/ Cmd to CK/ CK# domain: ± 70 mils (< 25ps).
 Maximum trace length difference (skew) DQS/DQS# to CK/ CK# domain: ± 250 mils (< 90ps).
7. Crosstalk control (Note: H is distance from reference layer):
 Keep edge-to-edge trace spacing within DQ/DM byte group > 2H
 Keep edge-to-edge trace spacing within Cmd/Add/Ctrl > 2H (commonly known as CA)
 Keep edge-to-edge trace separation for each group (DQ, DQS/DQS#, CA, CK/CK#) > 3H
8. DDR CLK differential termination 100ohm place at the end on DDR device. as close to CLK pins as possible.
9. Fly-By Topology & VTT Termination recommended for DDR3, if multiple devices are used.
10. Carefully consider layout requirements of DDRn vendor!!!

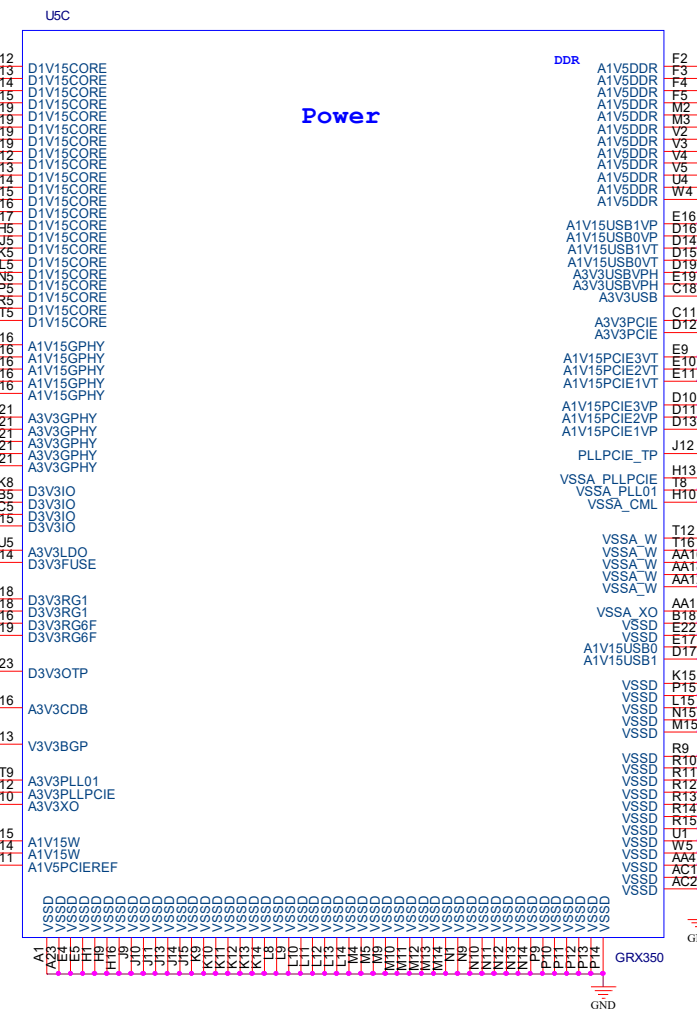
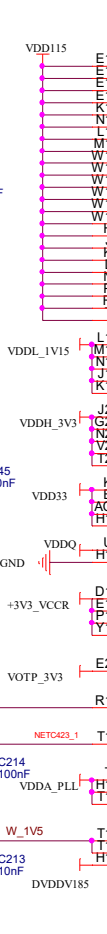
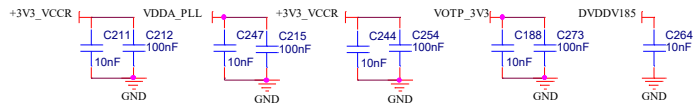




1. Connect D3V3RG1, D3V3RG6F to 3.3V individually, separate with others 3.3V by 0 ohm or Ferrite Bead.
2. Place 4 D-Caps for D3V3RG1, D3V3RG6F, decoupling capacitor need to be placed as near as possible to GRX350 power ball.
3. Every decoupling capacitor need to add a GND via to GND layer individually.

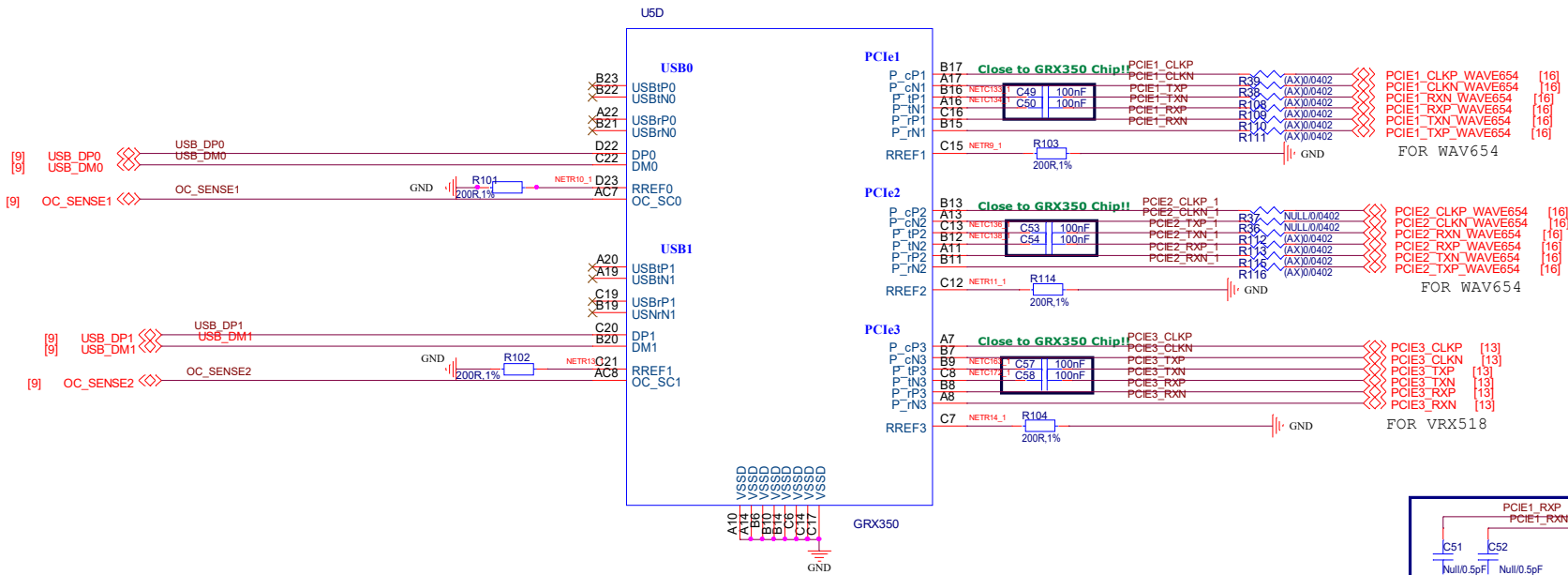


1. Connect V3V3BGP to 3.3V individually, separate with others 3.3V by Ferrite Bead.
2. Connect A3V3PLL01, A3V3PLLPCIE and A3V3XO to 3.3V (VDDA_PLL) individually, separate with others 3.3V by 0ohm or Ferrite Bead.
3. Connect A1V15W to 1.5V individually, separate with others 3.3V by 0ohm or Ferrite Bead.



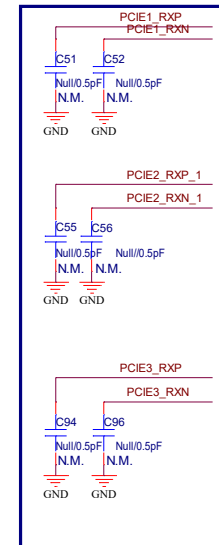
Power

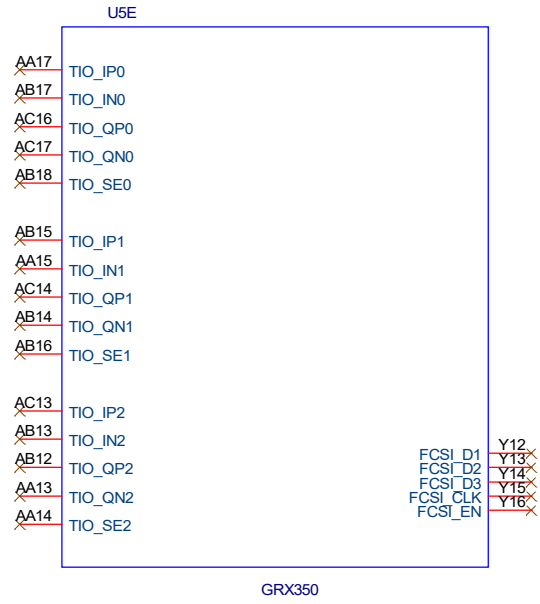
1. Connect A1V15USB0VP, A1V15USB1VP to 1.15V individually, separate with others 1.15V by 0 ohm or Bead.
 2. Connect A1V15USB0VT, A1V15USB1VT to 1.15V individually, separate with others 1.15V by 0 ohm or Bead.
 3. Connect A3V3USB, A3V3USBPTH to 3.3V individually, separate with others 3.3V by 0 ohm or Bead.
 4. Connect A1V15USB0, 1 to 1.15V individually, separate with others 1.15V by 0 ohm or Bead.
1. Connect A3V3PCIE to 3.3V individually separate with others 3.3V by 0 ohm or Bead.
 2. Connect A1V15PCIE1VT, A1V15PCIE2VT, A1V15PCIE3VT to 1.15V individually, separate with others 1.15V by 0 ohm or Bead.
 3. Connect A1V15PCIE1VP, A1V15PCIE2VP, A1V15PCIE3VP to 1.15V individually, separate with others 1.15V by 0 ohm or Bead.



1. An external Rref 200 ohm +/-1% resistor should be connect from the USB RREF0, RREF1 pins to ground. Place the Rref resistor close to RREF balls.
2. Place 2 AC coupling capacitors on USB TX pairs , <0.5inch length to GRX350 is recommended.
3. 90 ohm characteristic impedance control for USB differential signal routing. Keep the reference plane of signal continuous.
4. Match trace length of differential pairs (_p and _n signal) to given value in appropriate interface specification.
5. Populate sufficient GND vias nearby each PCIe differential pairs to tighten adjacent GND plane with GND layer.

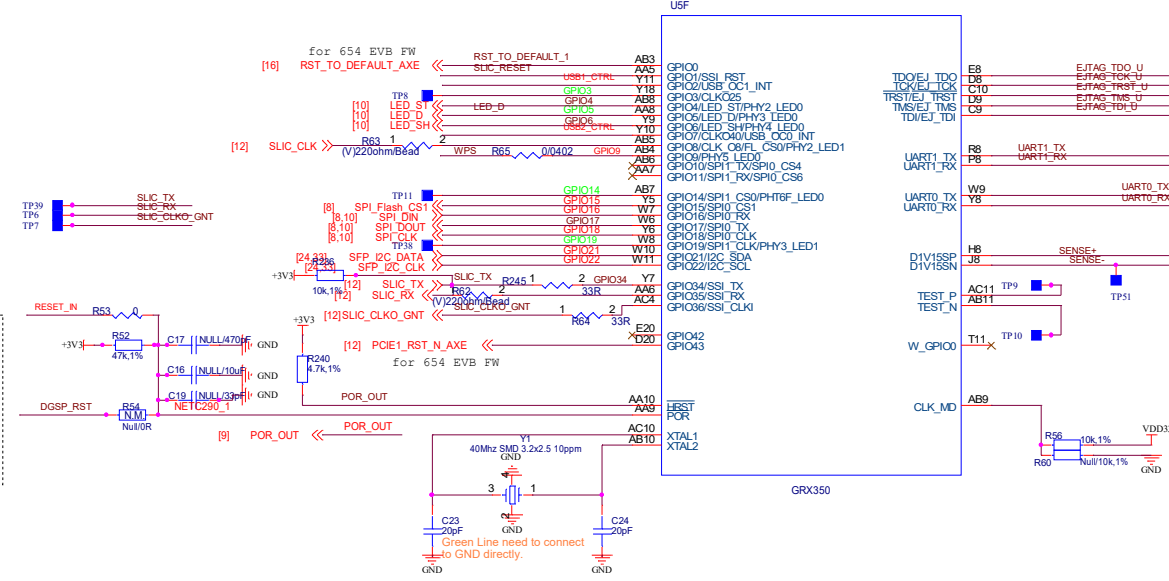
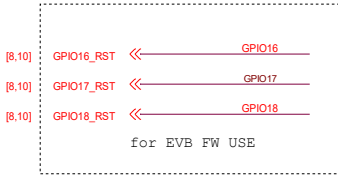
1. An external Rref 200 ohm +/-1% resistor should be connect from the 3 PCIe RREF pins to ground. Place the Rref resistors close to RREF balls.
2. Place 2 AC coupling capacitors on PCIe TX pairs , <0.5inch length to GRX350 is recommended.
3. 100 ohm characteristic impedance control for differential signal routing. Keep the reference plane of signal continuous.
4. In case with >= 2 PCIe differential pairs routing on PCB, a footprint of shielding case to enclose all these differential pairs is highly recommended for the compliance of EN300-328 V1.8.1 standard.
5. 0.5pF capacitors to ground on PCIe RX pairs, place them close to GRX350.
6. Match trace length of differential pairs (_p and _n signal) to given value in appropriate interface specification.
7. Populate sufficient GND vias nearby each PCIe differential pairs to tighten adjacent GND plane with GND layer.



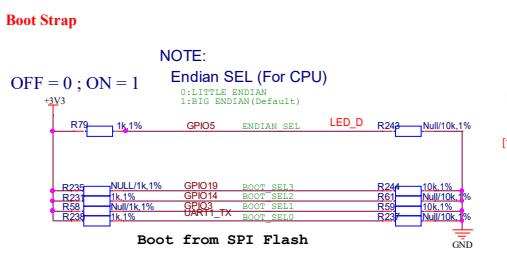
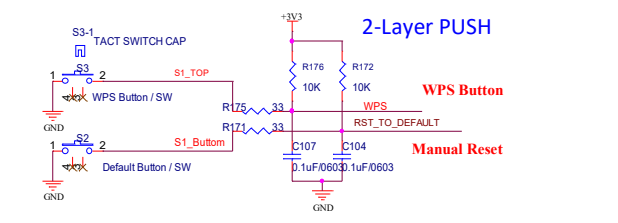
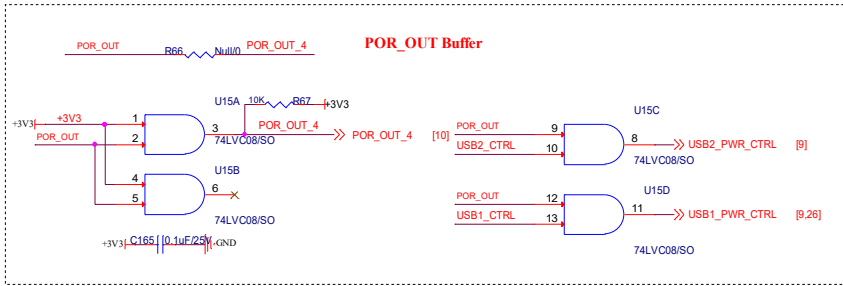
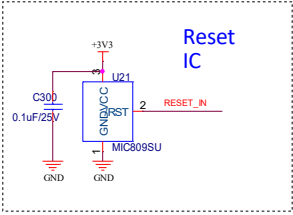
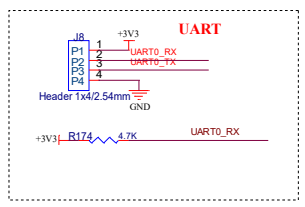


Trace capacitance for BBIO interface must be below 10pF!
 Recommend the maximum length should be under 3 inch.

<OrgName> DrayTek		
Title GRX350_BBIO		
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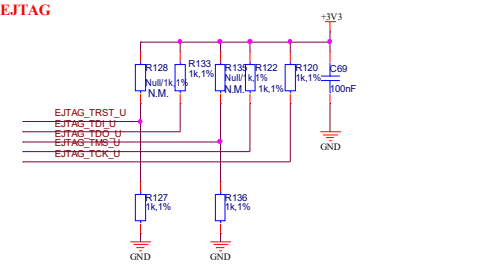
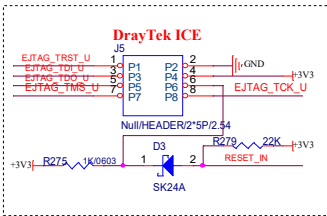
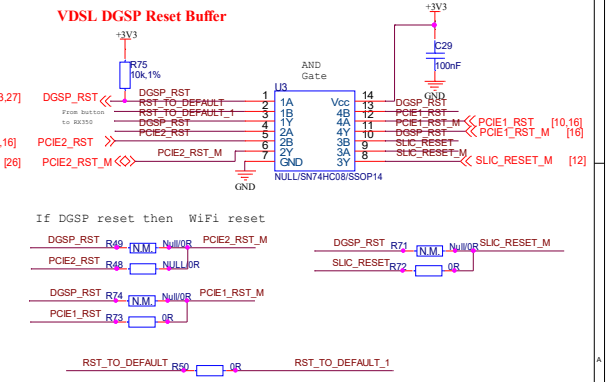
SENSE+/- routing on PCB should be differentially and Keep distance to switching sensitive component(e.g. inductors).

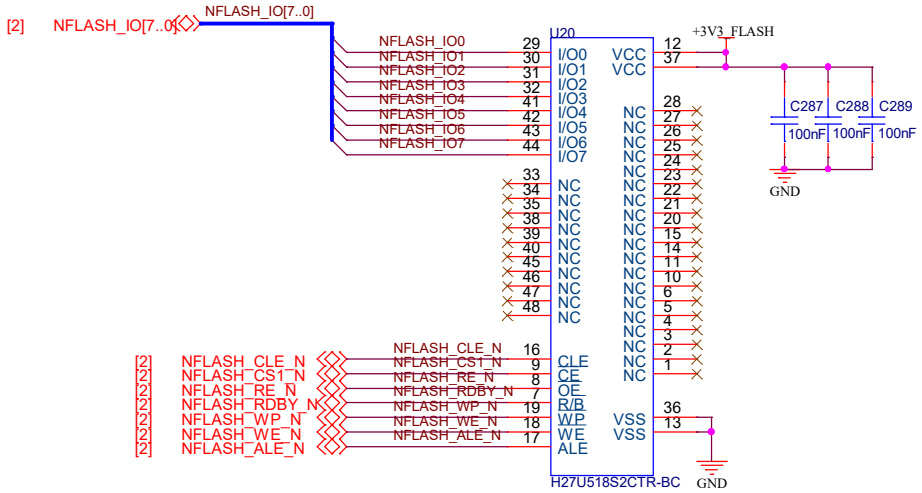


Strap Pin Setting Table

GPIO1 (BOOT_SEL1)	GPIO4 (BOOT_SEL2)	GPIO2 (BOOT_SEL1)	UART_TX (GPIO_SEL2)	Boot Source
0	0	1	0	UART via EEPROM
0	1	0	1	EEP ROM - (ELC type, ECC in NAND device)
0	1	0	0	EEP ROM - (ELC type, ECC in NAND device)
0	1	1	0	EEP ROM - (ELC type, ECC in NAND device)
0	1	0	1	EEP ROM - (ELC type, ECC in NAND device)
0	1	1	1	EEP ROM - (ELC type, ECC in NAND device)
1	0	0	0	EEPROM
1	0	1	0	EEPROM
1	0	0	0	EEPROM
1	0	1	0	EEPROM

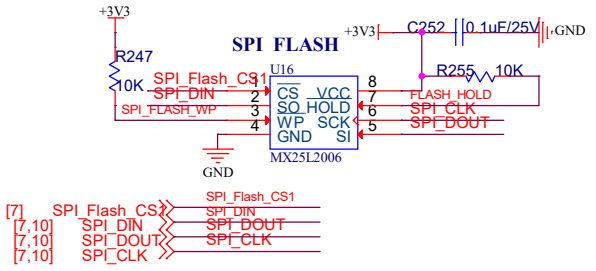
All other options are reserved/not used.



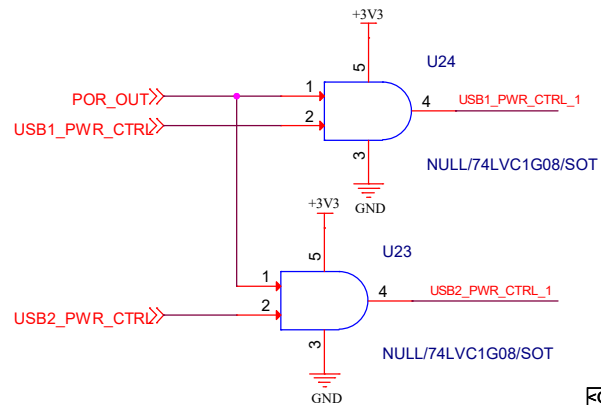
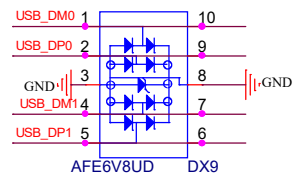
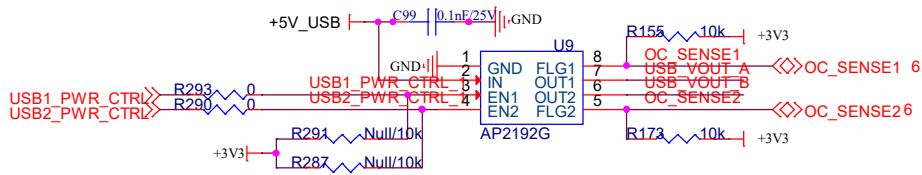
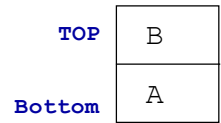
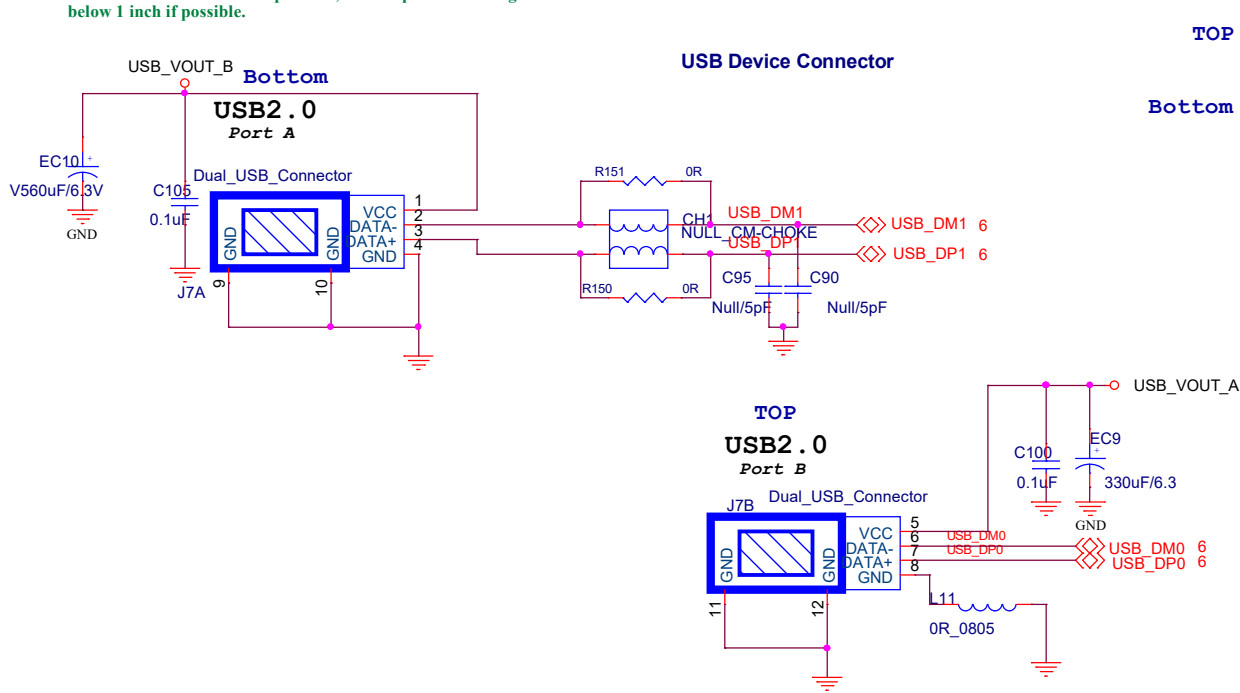


Qualified Nand Flash List

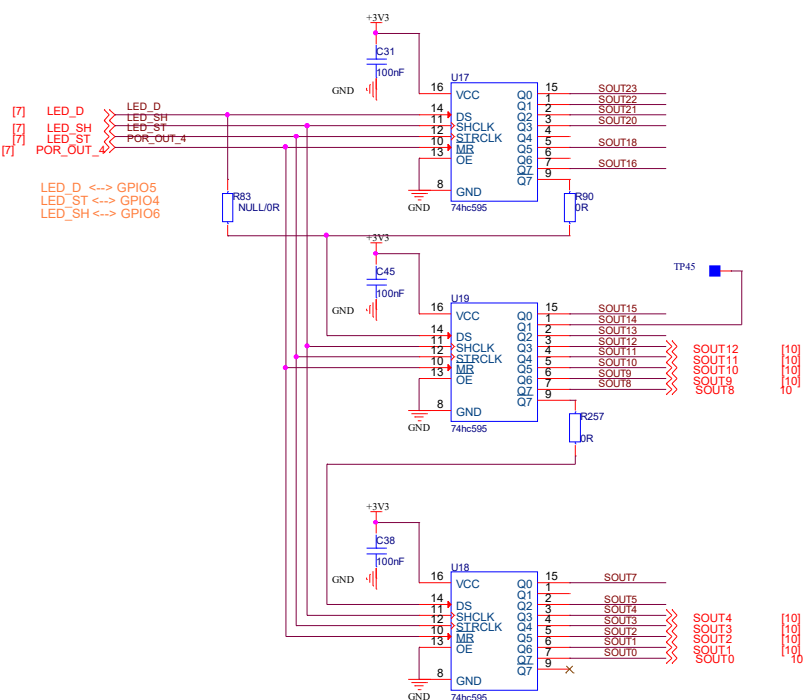
Vendor	Model
Hynix	H27uag8, 8k
Hynix	H27u512, 512
Hynix	H27u4g8f2dtr, 2k
Hynix	H27u1g8f2btf, 2k
Samsung	K9F1208, 512
Samsung	K9f1g08u0d, 2k
Samsung	K9g4g08u0b, 2k
Samsung	K9G8G08U0C, 8k
Spansion	S34ml01g100, 2k
Mircon	29f64g08cbaba, 8k
Mircon	29f32g08cbaca, 4k
Infineon	Hyf33ds51280, 512
Toshiba	Th58BVG3S0HTA00, 4k



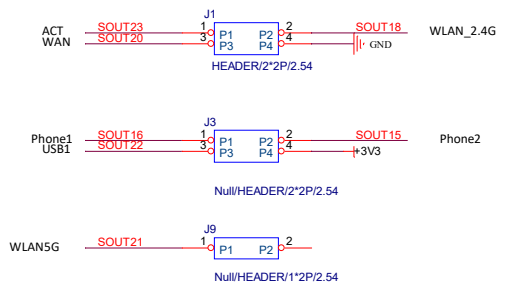
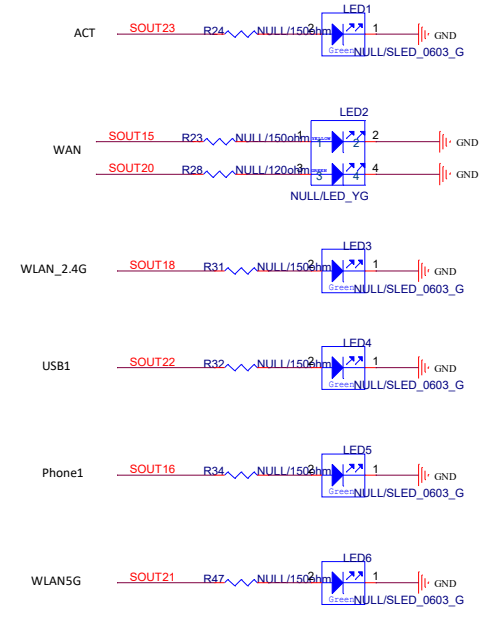
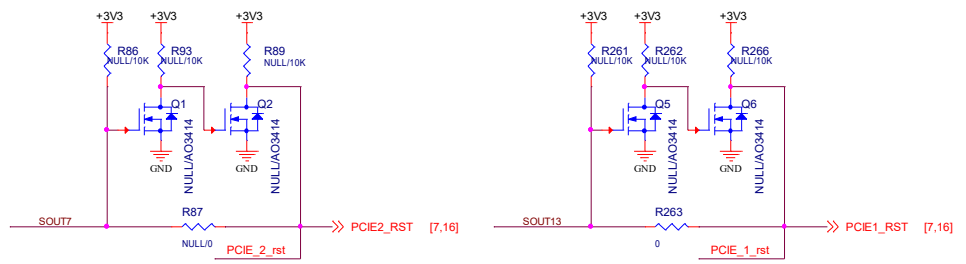
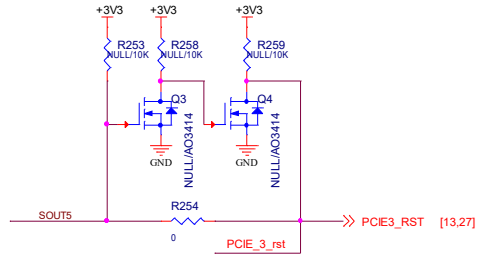
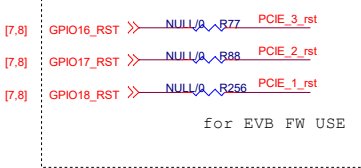
!!Note:
The PCB layout of the differential signal DP and DM should have 90 ohm differential impedance, and keep the trace length below 1 inch if possible.



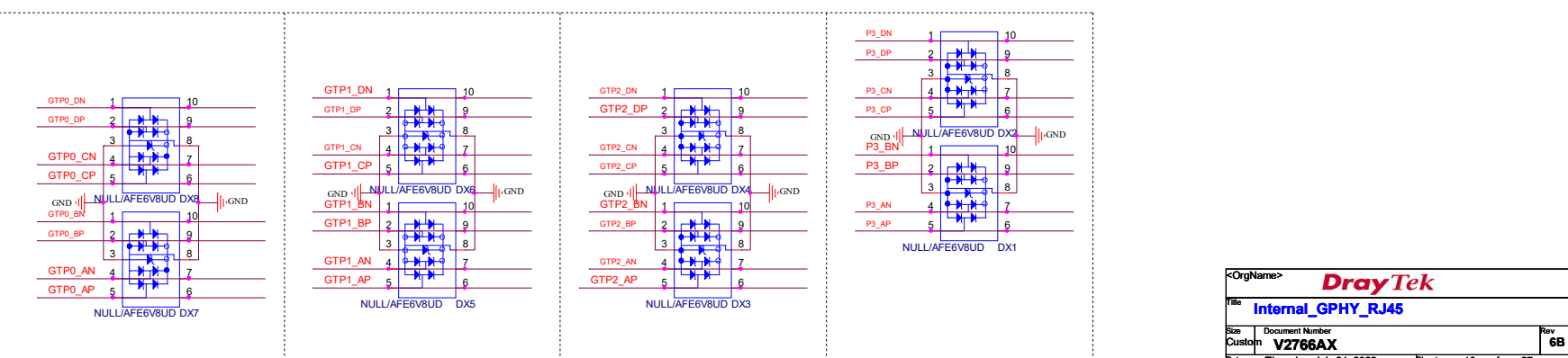
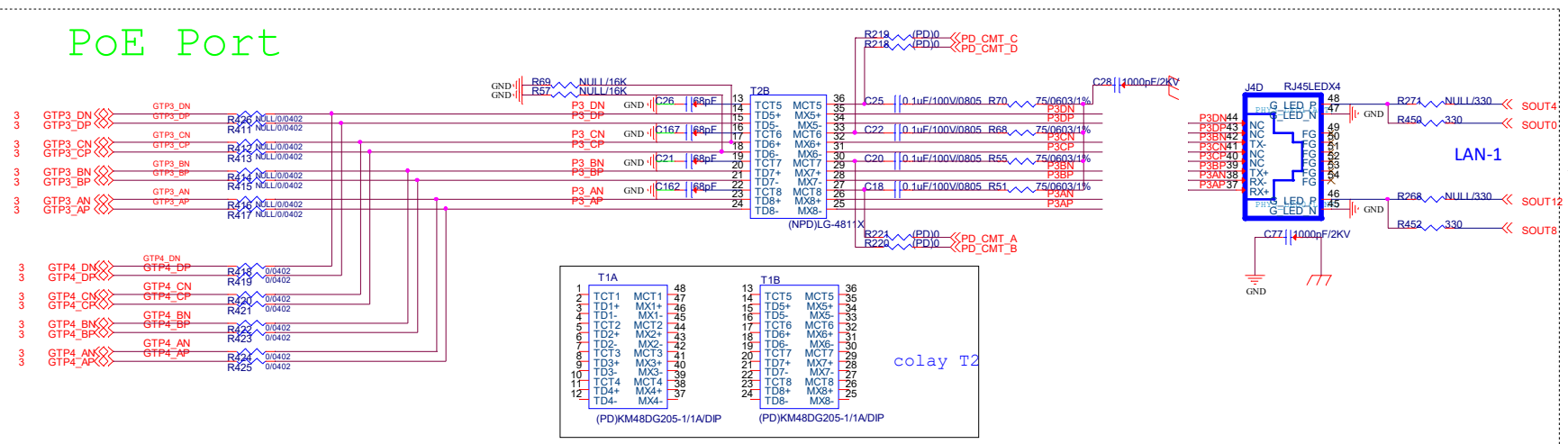
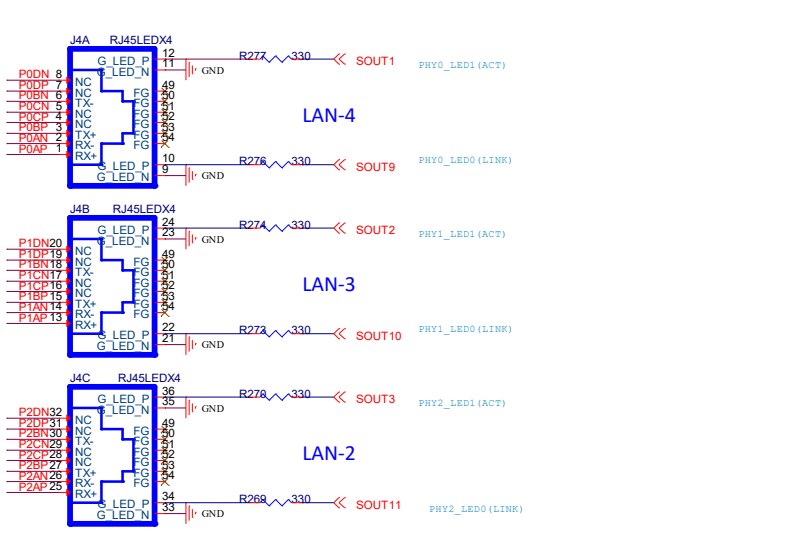
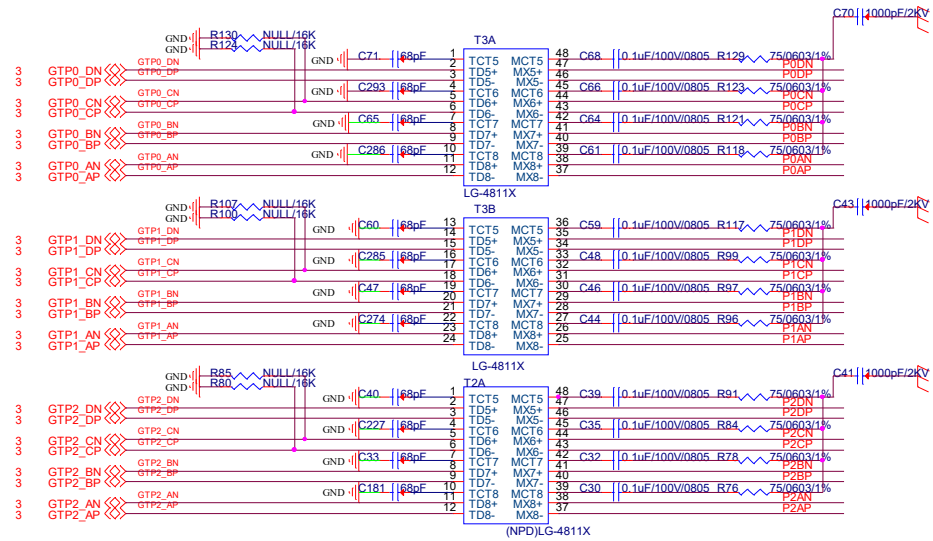
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Title USB_Port		
Size B	Document Number V2766AX	Rev 6B
Date: Thursday, July 21, 2022	Sheet 08 of 27	



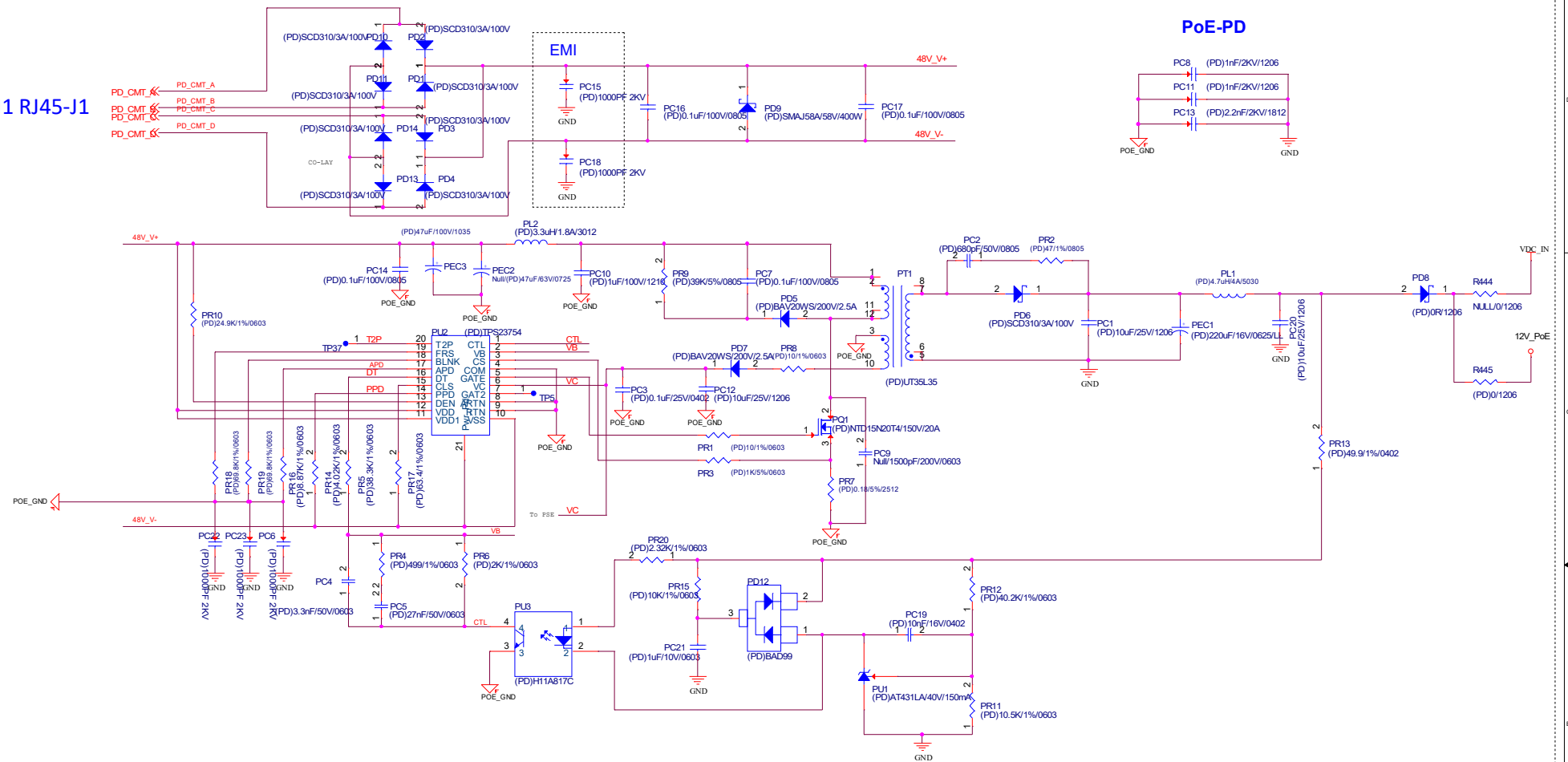
LED_D <-> GPIO5
LED_ST <-> GPIO4
LED_SH <-> GPIO6



<OrgName> DrayTek		
Title GPIO_LED		
Size Custom	Document Number V2766AX	Rev 6B
Date: Thursday, July 21, 2022	Sheet 10	of 34

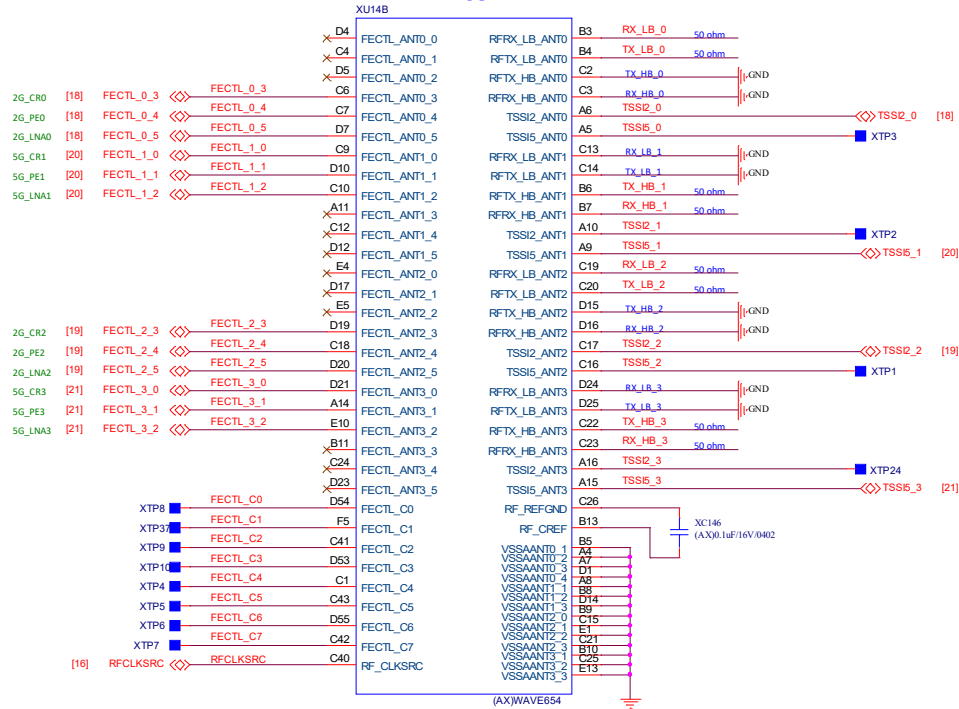


To LAN1 RJ45-J1



<OrgName> DrayTek	
File	POE PD
Size	Document Number
C	V2766AX
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Rev	6B

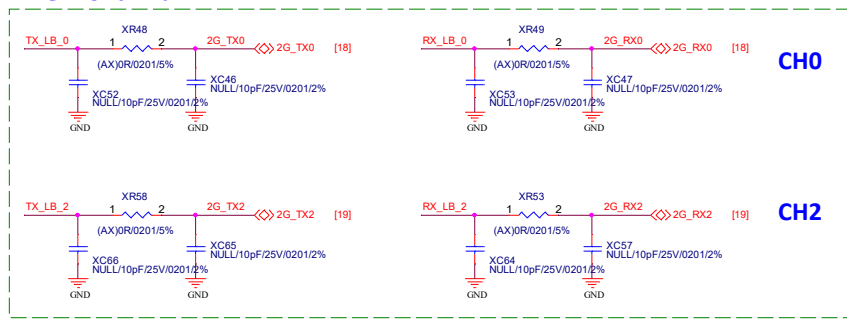
WAVE654 RF



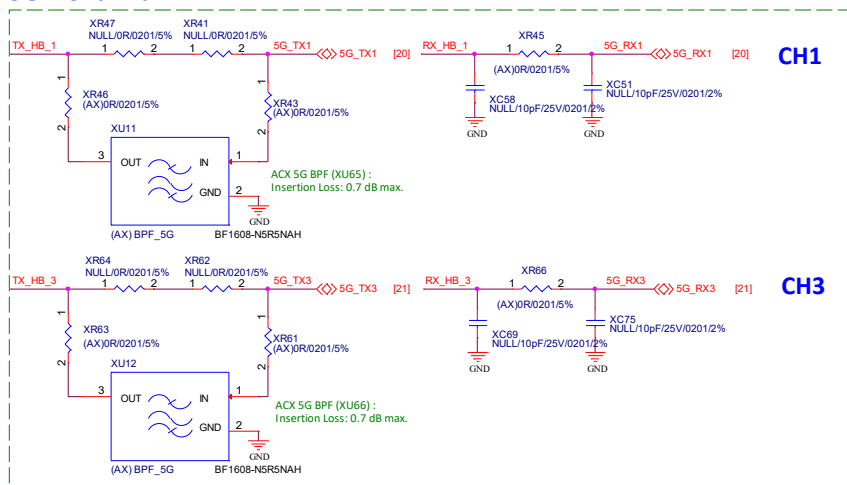
Reserved for GPB654 Reference Design

PCIE FINGER

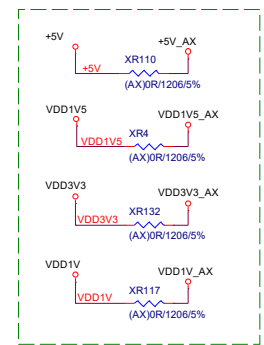
2.4G Front-End



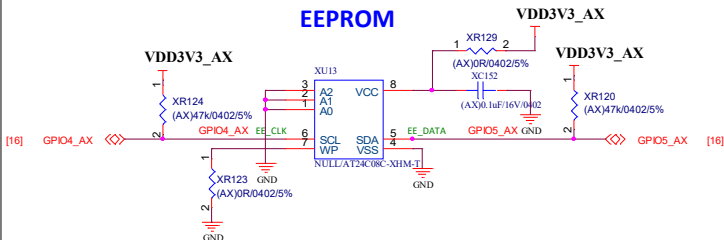
5G Front-End



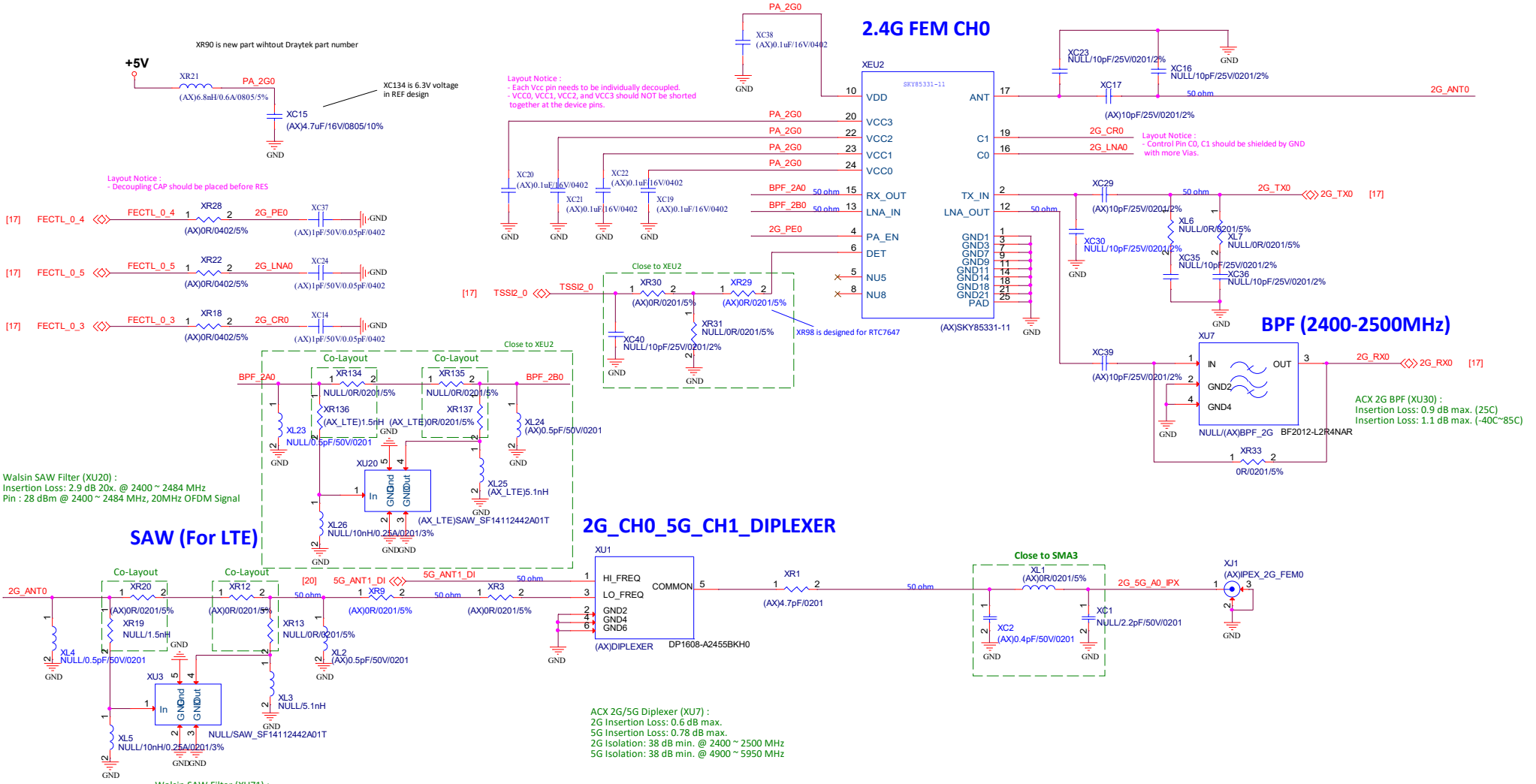
Connect to main board DCDC



SY98004 : Vout=0.6[1+120K/165K]=1.036V
WAV654 Range : 0.72V ~ 1.05V



SKY85331-11 :
 Output power: +22 dBm @ 1.8% EVM, HT40, MCS9, 5 V
 Output power: +26 dBm @ 3% EVM, HT40, MCS7, 5 V



Walsin SAW Filter (XU20) :
 Insertion Loss: 2.9 dB 20x. @ 2400 ~ 2484 MHz
 Pin : 28 dBm @ 2400 ~ 2484 MHz, 20MHz OFDM Signal

SAW (For LTE)

2G_CH0_5G_CH1_DIPLEXER

ACX 2G/5G Diplexer (XU7) :
 2G Insertion Loss: 0.6 dB max.
 5G Insertion Loss: 0.78 dB max.
 2G Isolation: 38 dB min. @ 2400 ~ 2500 MHz
 5G Isolation: 38 dB min. @ 4900 ~ 5950 MHz

Walsin SAW Filter (XU71) :
 Insertion Loss: 2.2 dB typ. 2.9 dB max. @ 2400 ~ 2484 MHz (-30 ~ +85C)
 Pin : 28 dBm @ 2400 ~ 2484 MHz

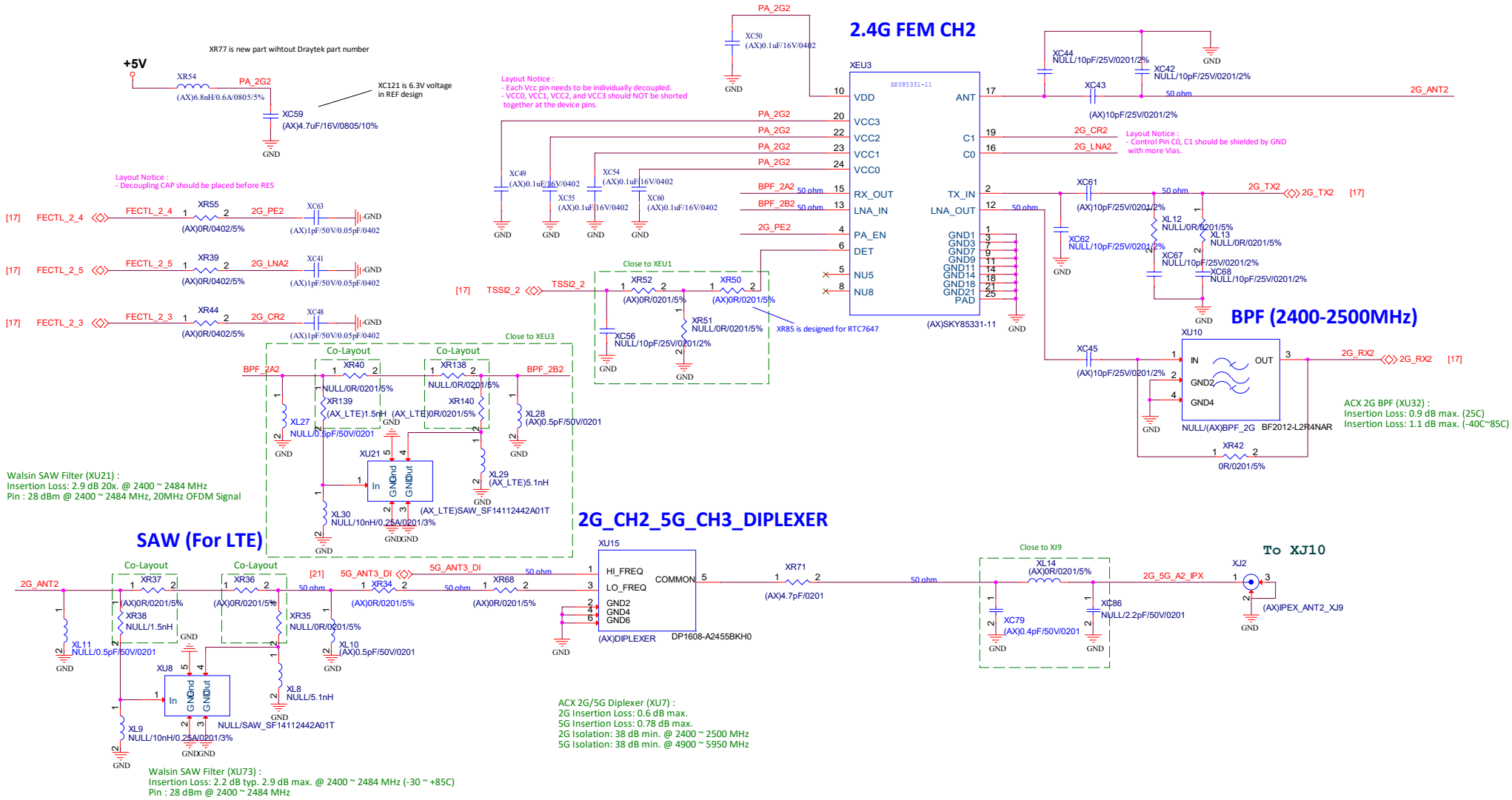
BPF (2400-2500MHz)

ACX 2G BPF (XU30) :
 Insertion Loss: 0.9 dB max. (25C)
 Insertion Loss: 1.1 dB max. (-40C~85C)

<OrgName>		DrayTek	
File		RF_2.4G_FEM_CH0	
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Custom	V2766AX	6B	
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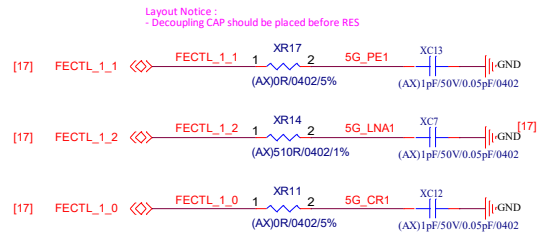
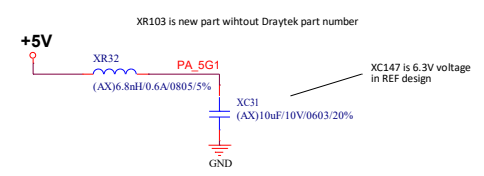
SKY85331-11 :
 Output power: +22 dBm @ 1.8% EVM, HT40, MCS9, 5 V
 Output power: +26 dBm @ 3% EVM, HT40, MCS7, 5 V

2.4G FEM CH2

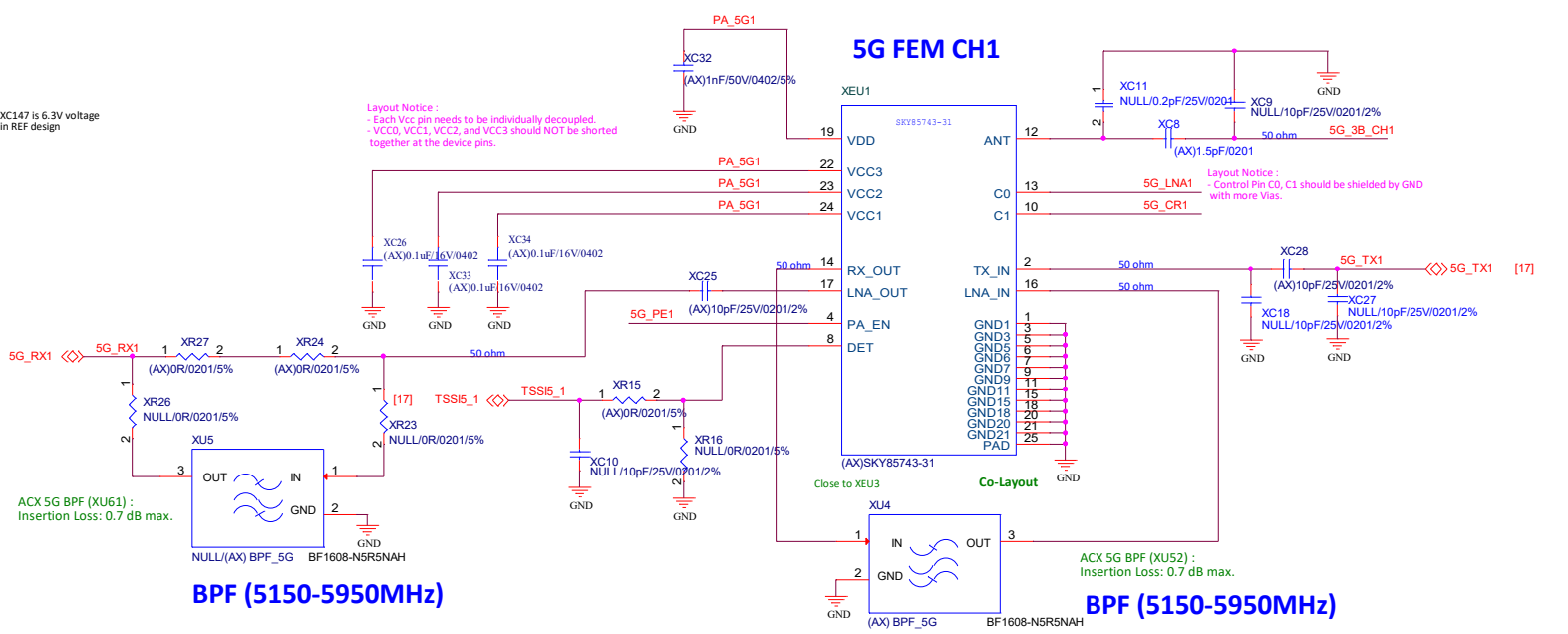


<OrgName>		DrayTek	
File		RF_2.4G_FEM_CH2	
Size	Document Number	Rev	
Custom	V2766AX	6B	
Date:		Thursday, July 21, 2022	Sheet 19 of 34

SKY85743-31 :
 Output power: +21 dBm, -43 dB DEVM, MCS11
 Output power: +22 dBm, -40 dB DEVM, MCS11
 Output power: +24 dBm, -35 dB DEVM, MCS9



Layout Notice :
 - Each Vcc pin needs to be individually decoupled.
 - VCC0, VCC1, VCC2, and VCC3 should NOT be shorted together at the device pins.



BPF (5150-5950MHz)

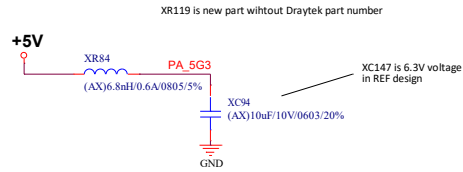
BPF (5150-5950MHz)

BPF (5150-5950MHz)

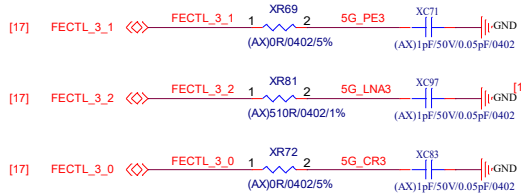
5G_ANT1

<OrgName>			DrayTek
File			RF_5G_FEM_CH1
Size	Document Number	Rev	
Custom	V2766AX	6B	
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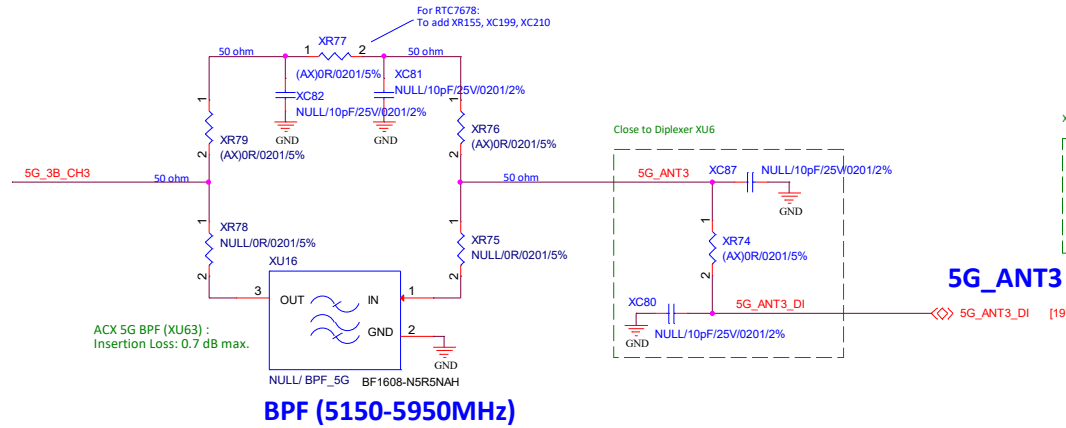
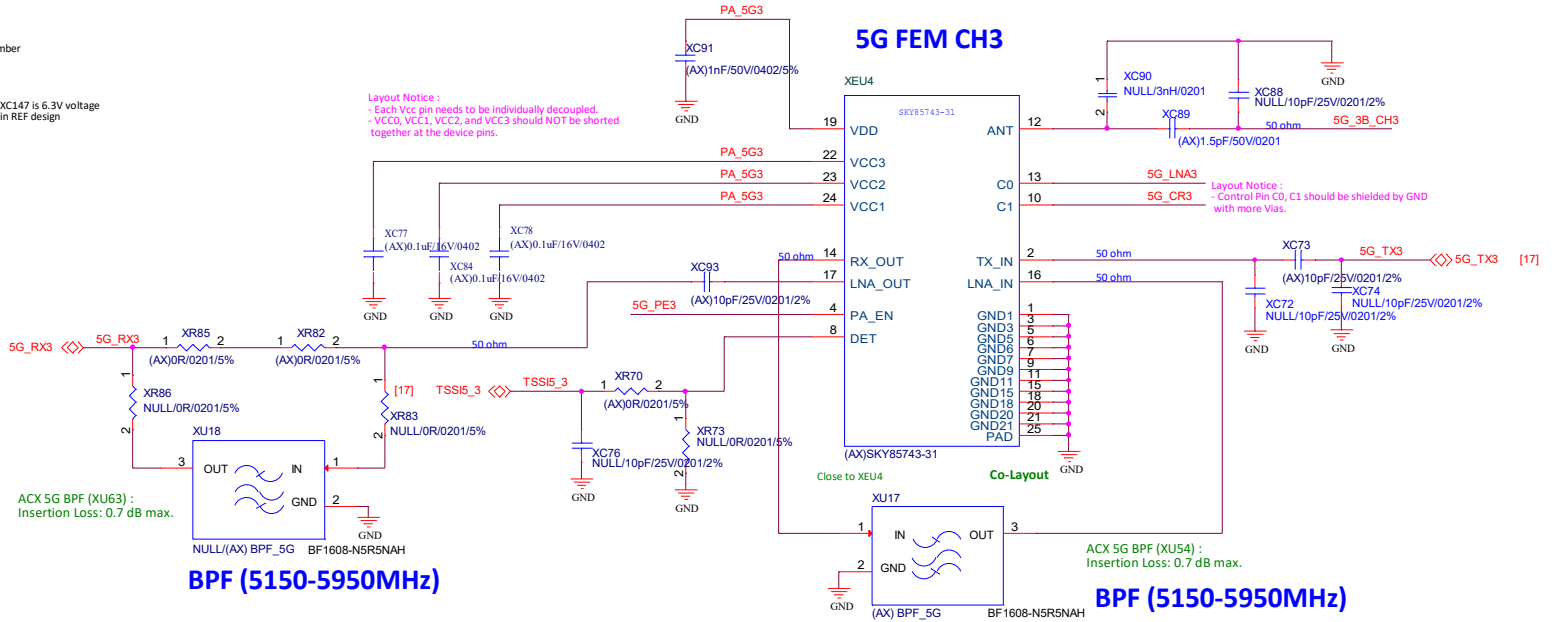
SKY85743-31:
 Output power: +21 dBm, -43 dB DEVM, MCS11
 Output power: +22 dBm, -40 dB DEVM, MCS11
 Output power: +24 dBm, -35 dB DEVM, MCS9



Layout Notice:
 - Decoupling CAP should be placed before RES

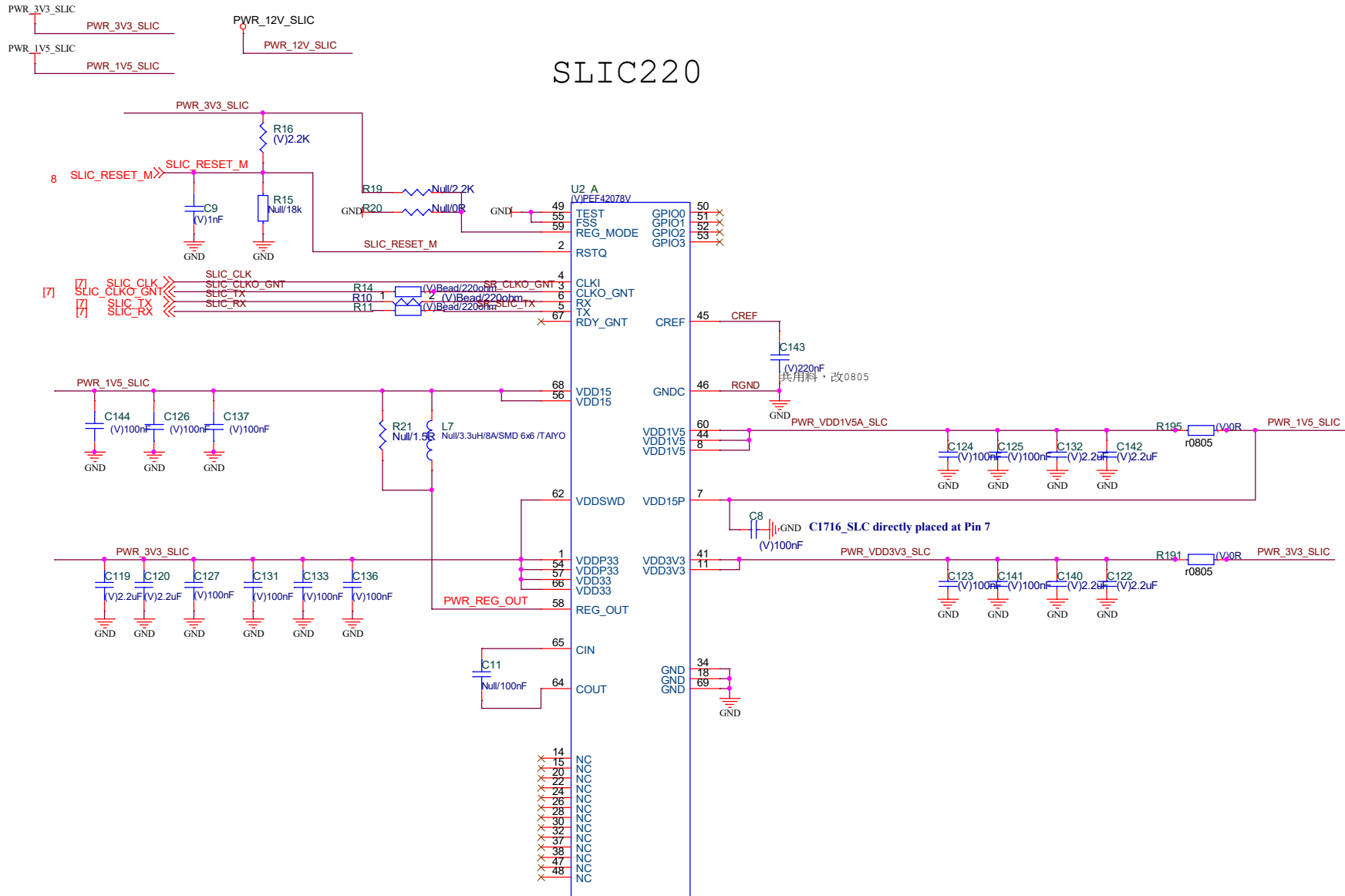


Layout Notice:
 - Each Vcc pin needs to be individually decoupled.
 - VCC0, VCC1, VCC2, and VCC3 should NOT be shorted together at the device pins.



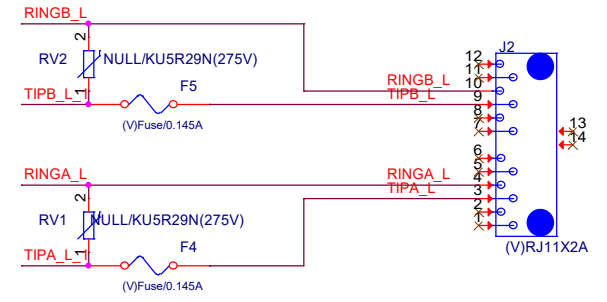
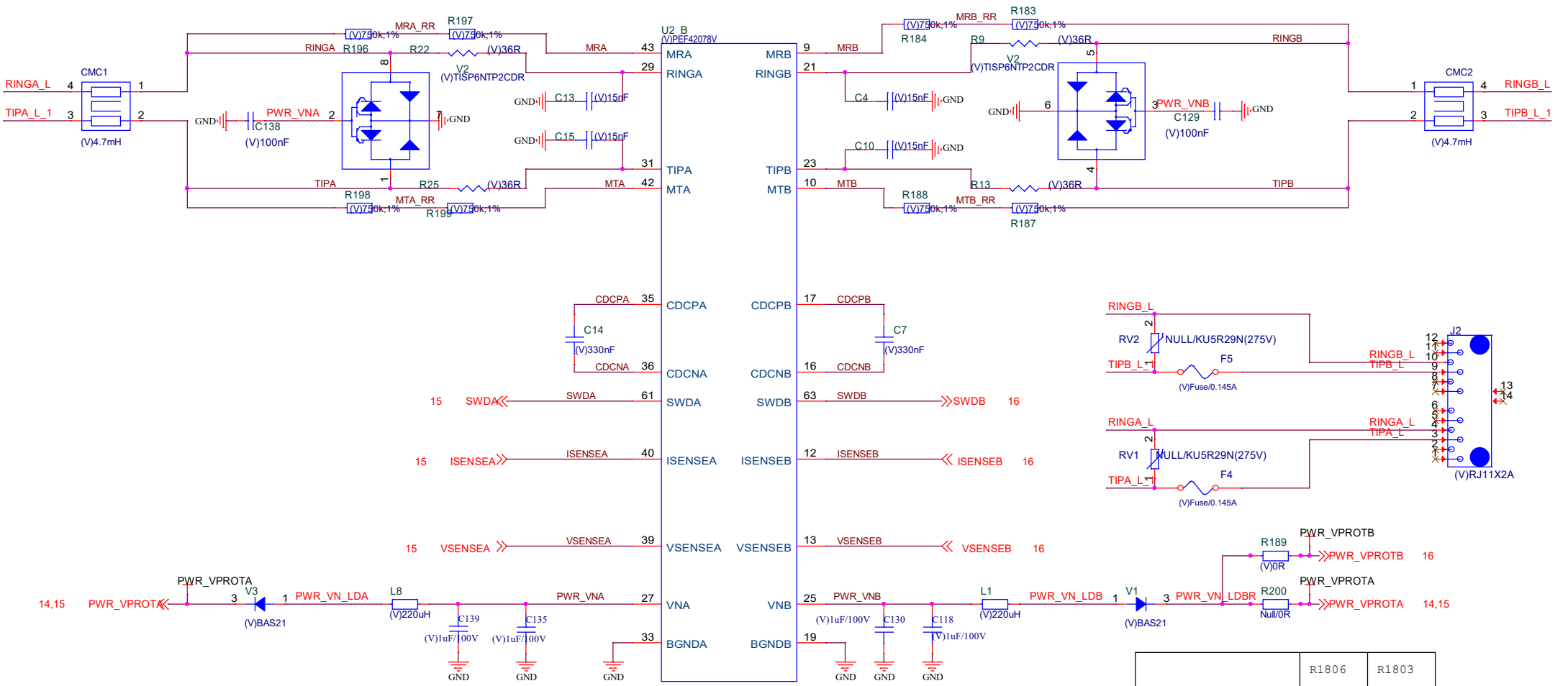
<OrgName>		DrayTek	
File		RF_5G_FEM_CH3	
Size	Document Number	Rev	
Custom	V2766AX	6B	
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SLIC220



<OrgName>		DrayTek	
Title		XWAYS LIC220_DIGITAL	
Size	Document Number	Rev	
Custom	V2766AX		6B
Date:	Thursday, July 21, 2022	Sheet	22 of 27

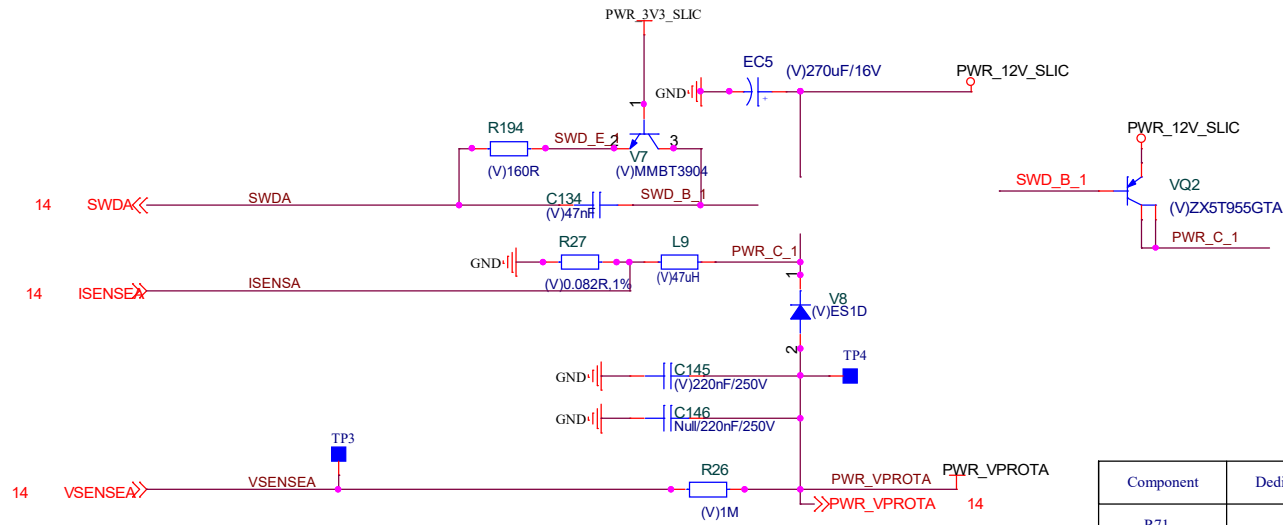
SLIC220



	R1806	R1803
Dedicated DCDC mode	Mounted	X
Combined DCDC mode	X	Mounted

DCDC Type
 Dedicated DCDC = T0.2
 Combined DCDC = T1.1

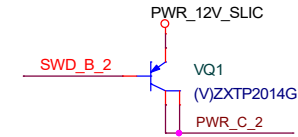
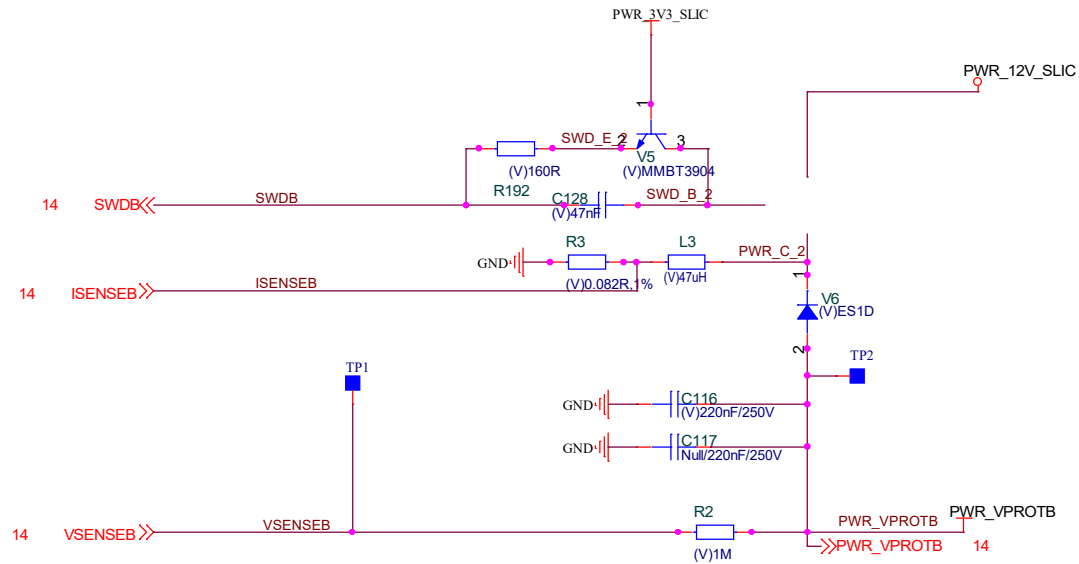
Move radiating parts (like switching regulators and coils, voice SLIC/coils,) far away from DSL-AFE. A distance (at least 5cm) between the radiating part and the DSL must maintain.



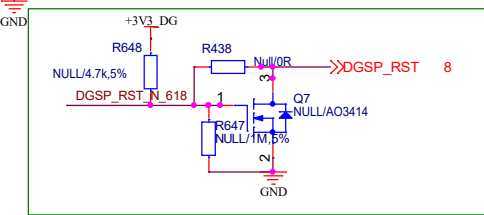
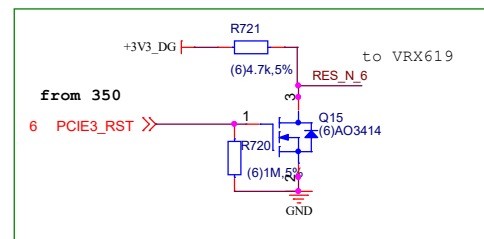
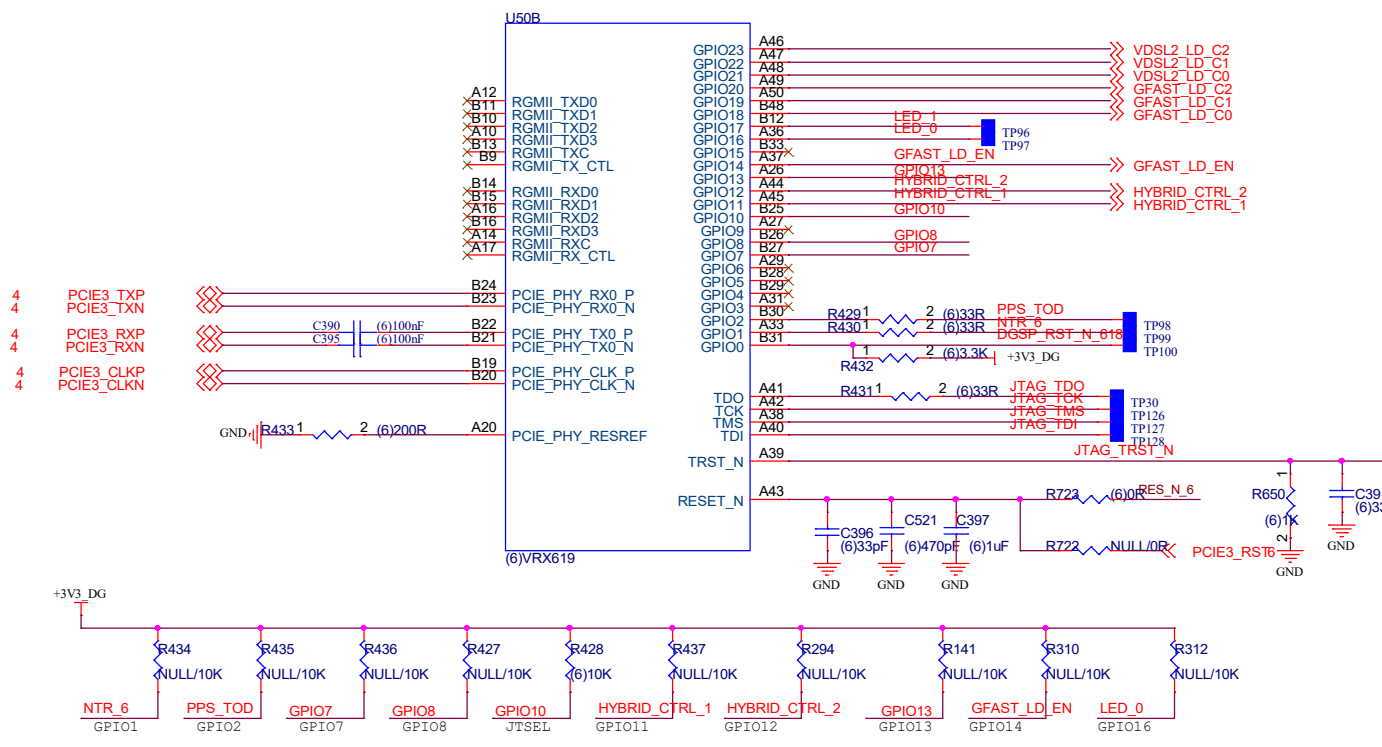
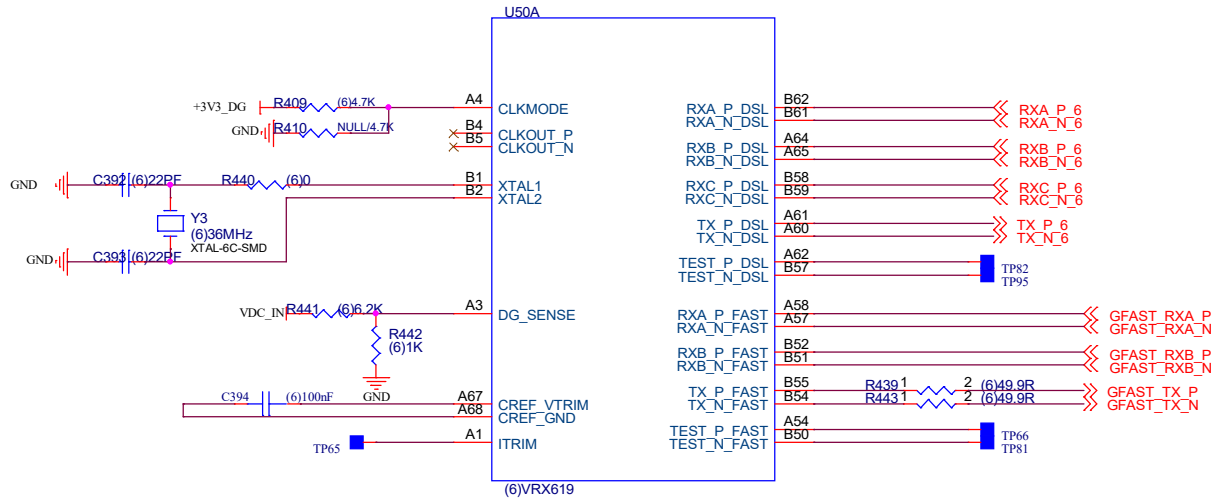
Component	Dedicated DCDC	Combined DCDC
R71	0.082R	0.068R
L7	47uH/1.8A	33uH/2.1A
C196	mount	X
C1805	X	mount

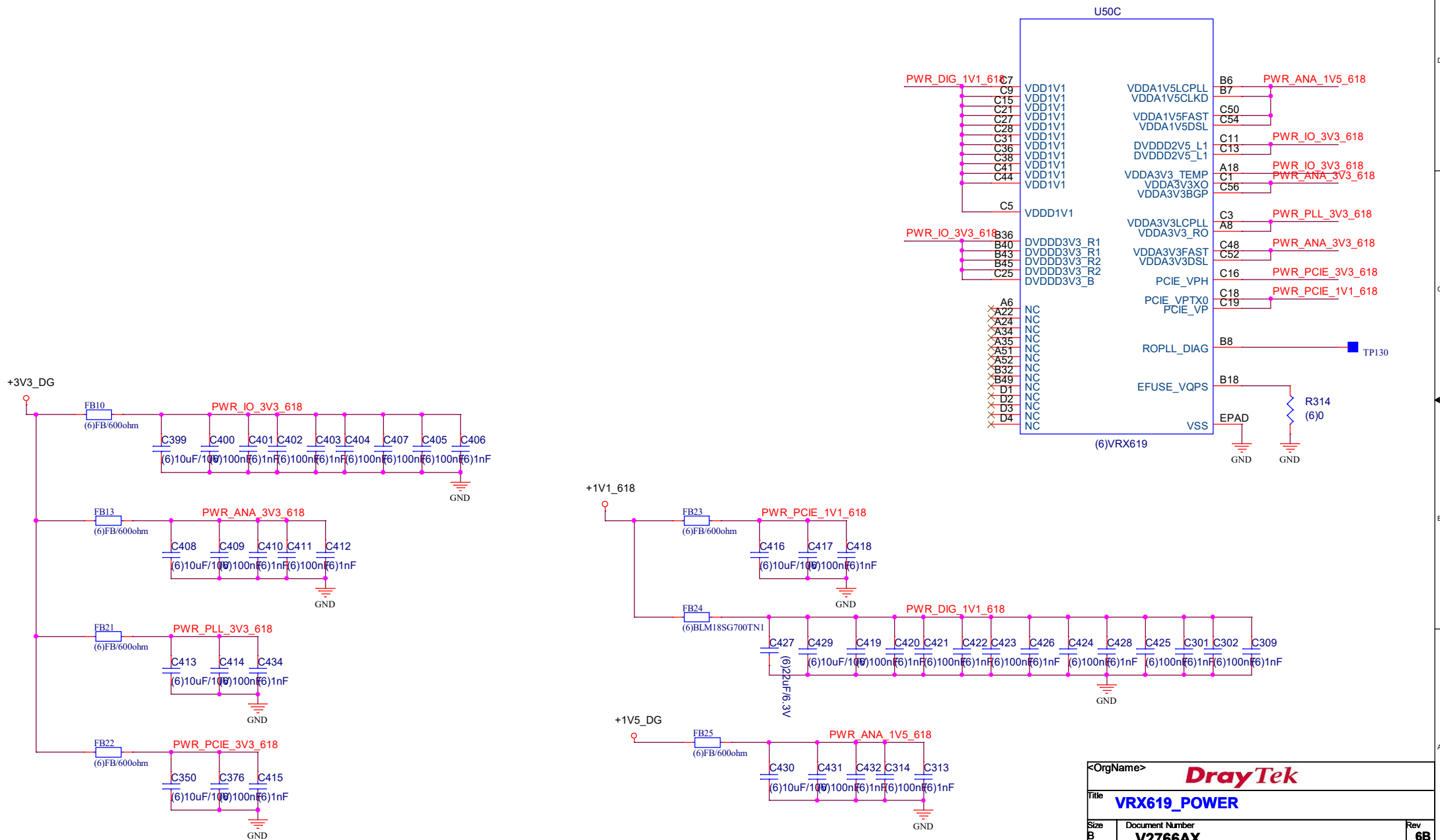
DCDC Type
 Dedicated DCDC = T0.2
 Combined DCDC = T1.1

Move radiating parts (like switching regulators and coils, voice SLIC/coils,) far away from DSL-AFE. A distance (at least 5cm) between the radiating part and the DSL must be maintain.

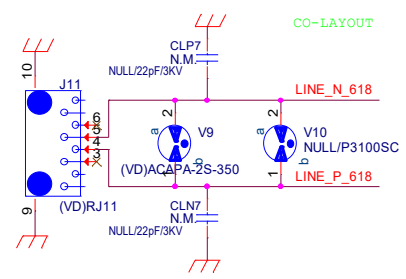
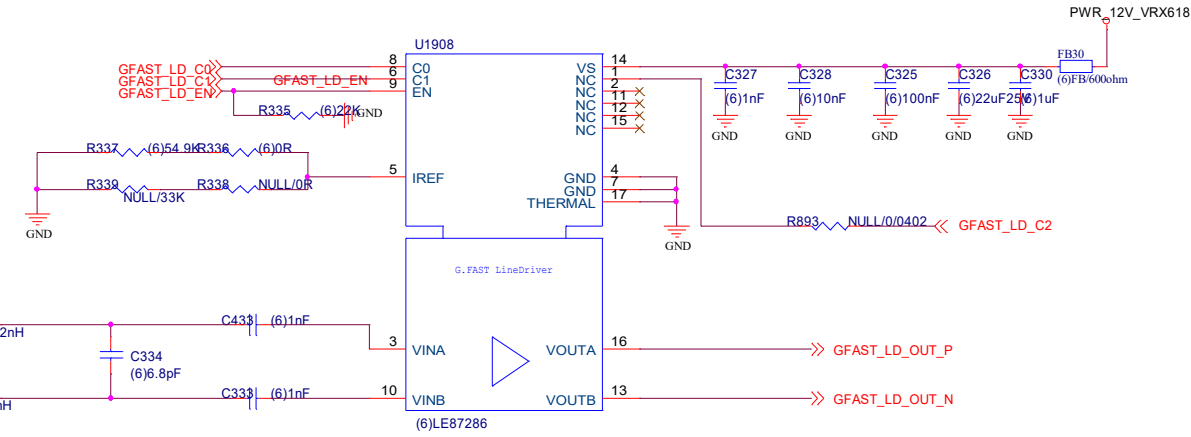
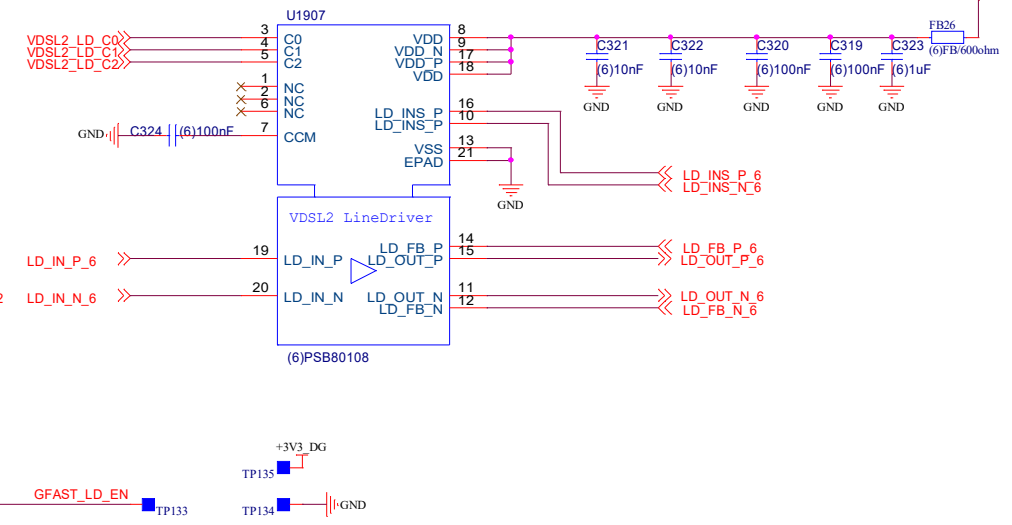
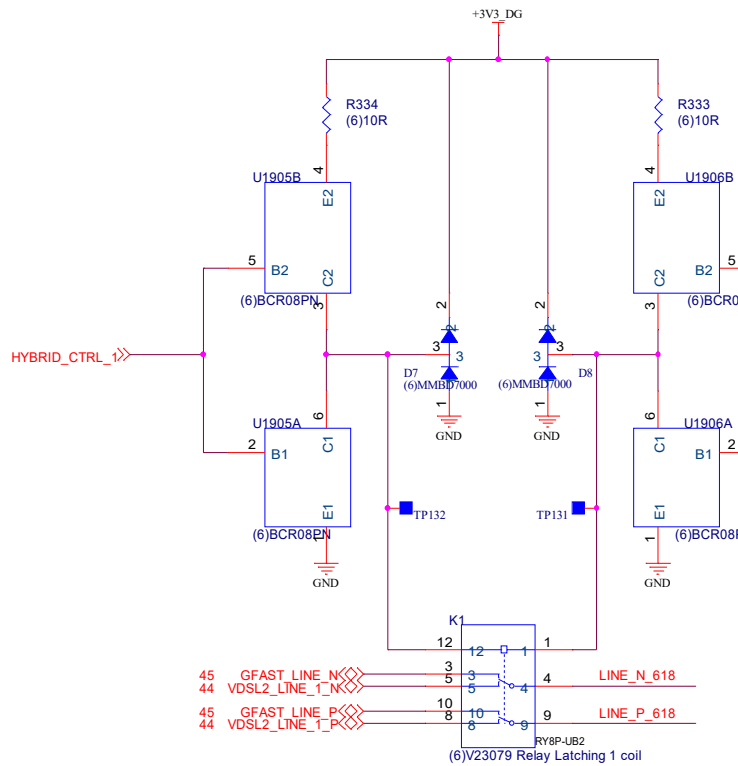


Component	Dedicated DCDC	Combined DCDC
R77	0.082R	0.068R
L9	47uH/1.8A	33uH/2.1A
C204	mount	X
C1806	X	mount



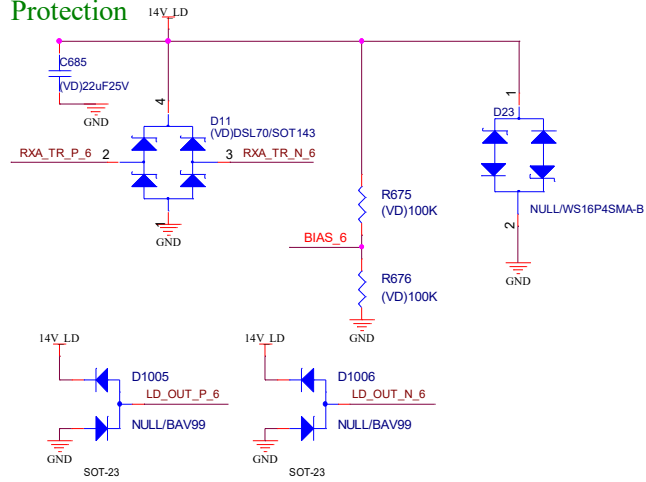


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DrayTek		
Title		
VRX619_POWER		
Size	Document Number	Rev
B	V2766AX	6B
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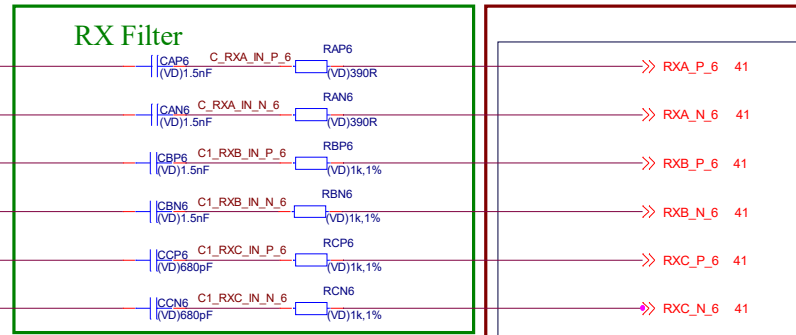


<OrgName>		DrayTek	
Title		VRX619_Relay_Line driver	
Size	Document Number	Rev	
Custom	V2766AX	6B	
Date:	Thursday, July 21, 2022	Sheet	28 of 40

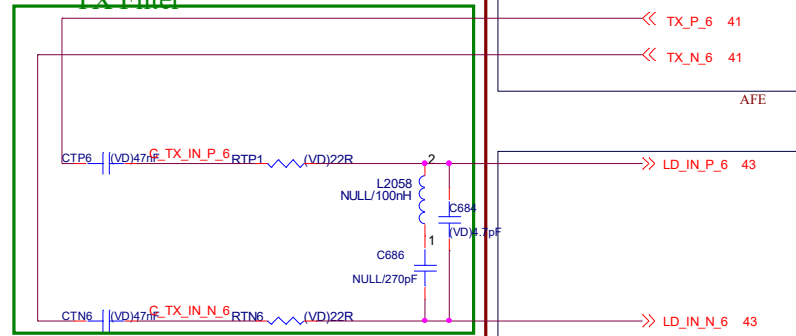
Protection



RX Filter

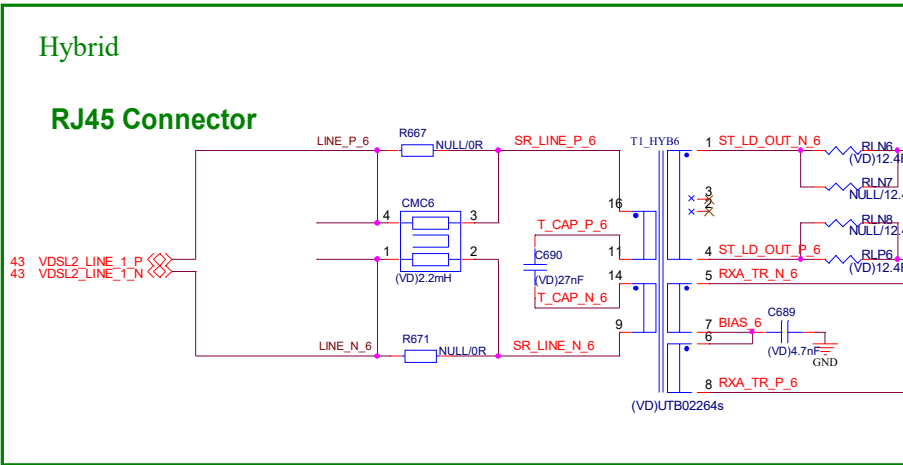


TX Filter

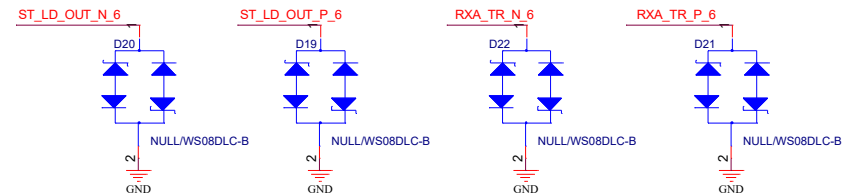


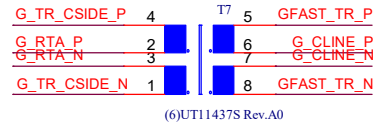
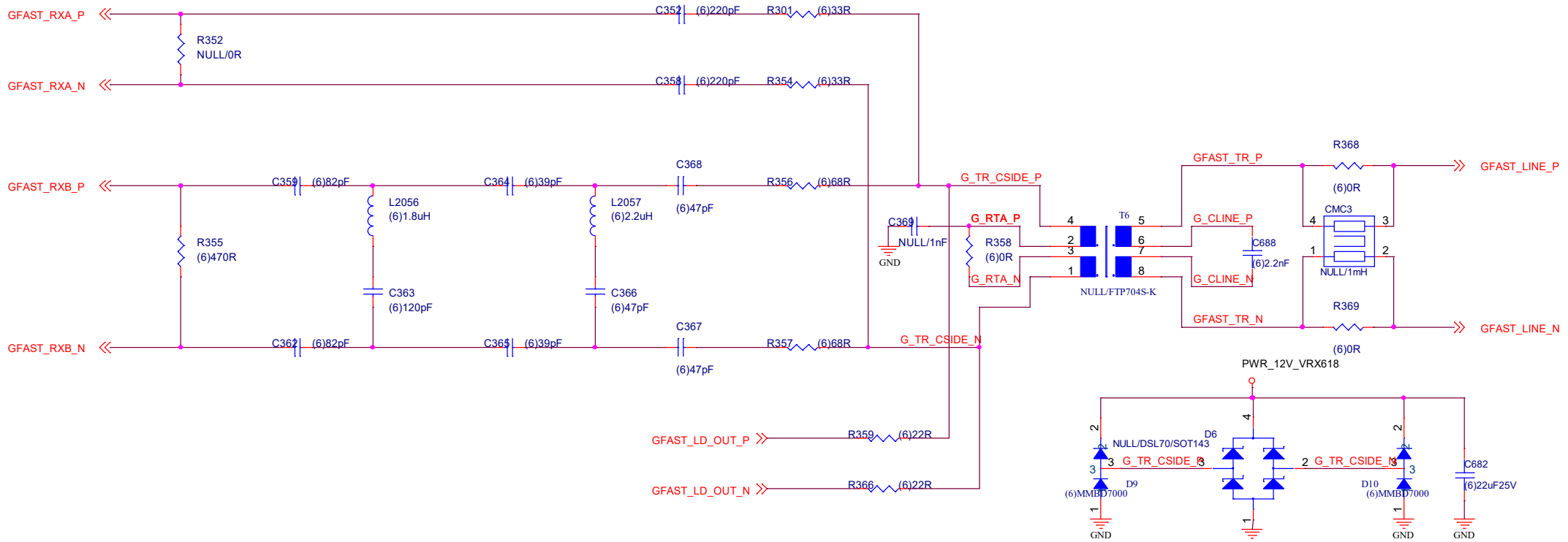
Hybrid

RJ45 Connector



for VRX619 Line Driver

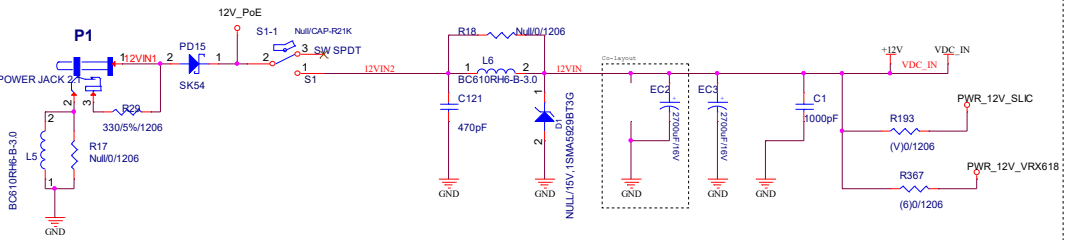




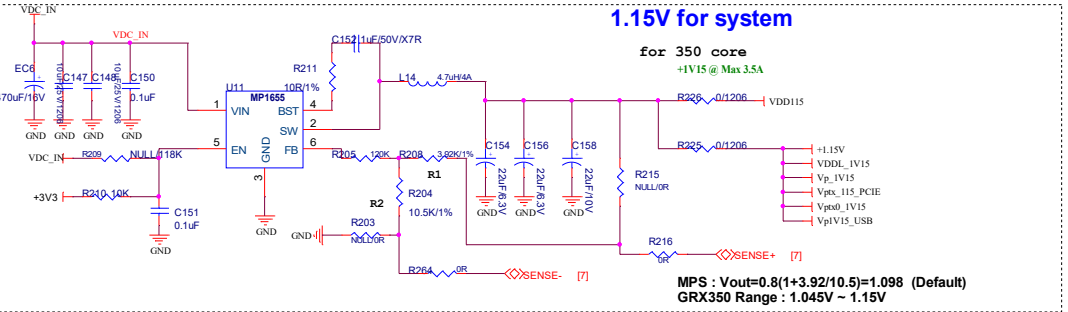
(6)UT11437S Rev.A0

<OrgName>		DrayTek	
Title		VRX619_GFAST_Hybrid	
Size	Document Number	Rev	
Custom	V2766AX		6B
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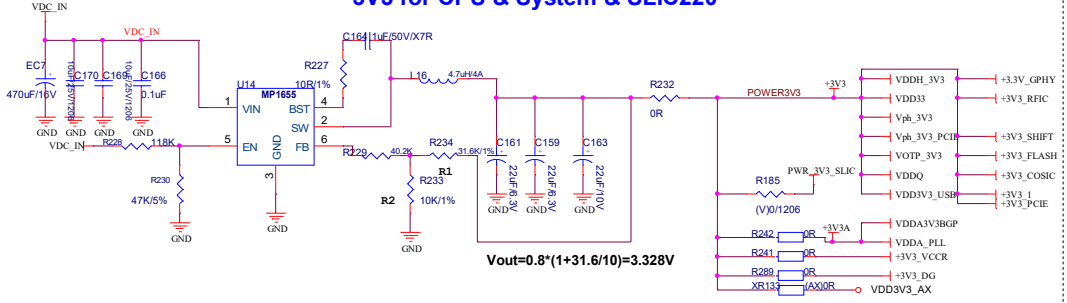
12V DC Power Input



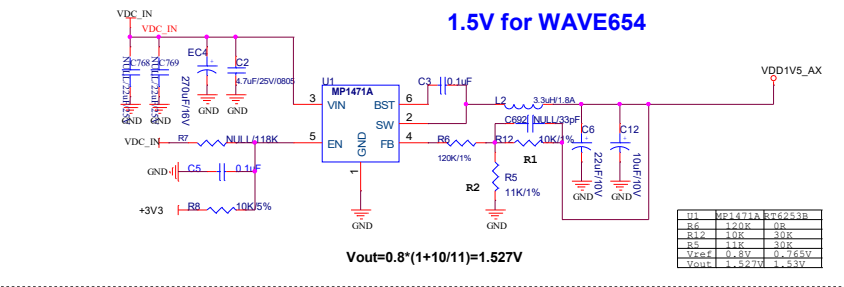
1.15V for system



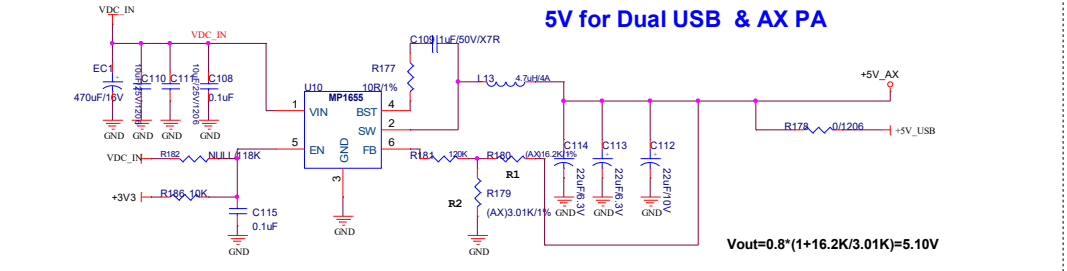
3V3 for CPU & System & SLIC220



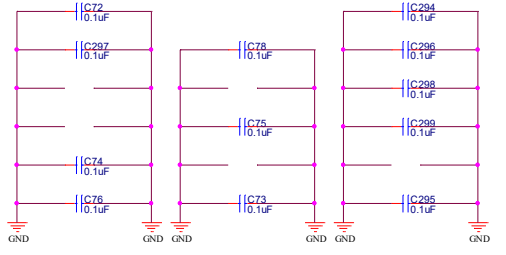
1.5V for WAVE654



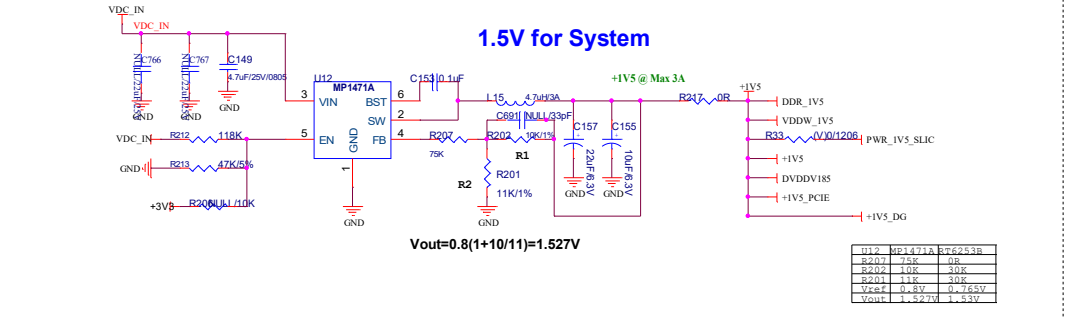
5V for Dual USB & AX PA



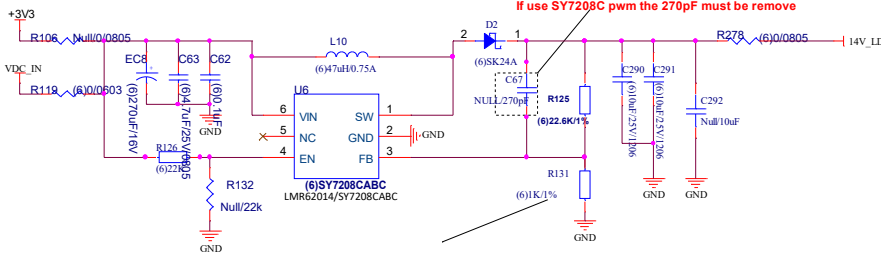
for VRX619 Z12M noise isolation



1.5V for System



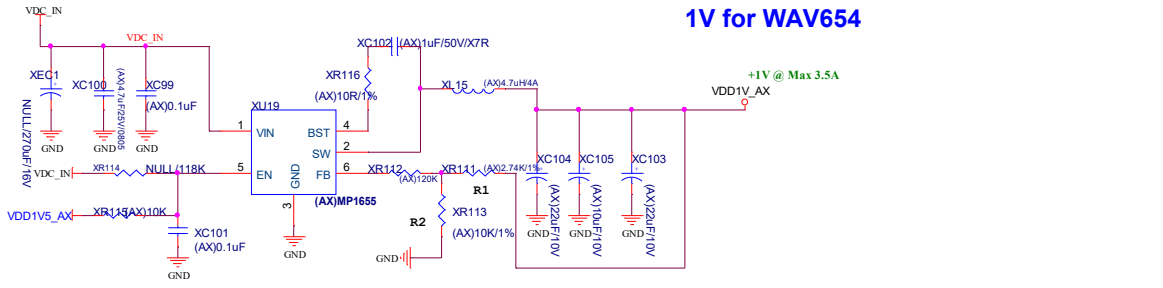
DC to DC Boost 12V to 14V circuitry



Silergy SY7208C $V_{out} = 0.6 * (1 + 22.6/1) = 14.16V$

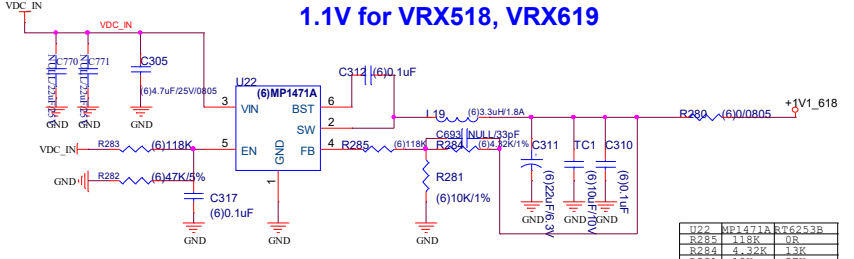
If use SY7208C pwm the 270pF must be remove

1V for WAV654



MPS : $V_{out} = 0.8 * (1 + 2.74/10) = 1.0192$ (Default)
WAV654 Range : 0.72V ~ 1.05V

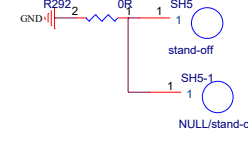
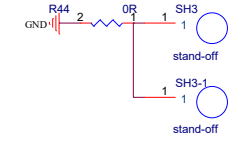
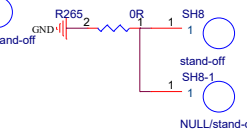
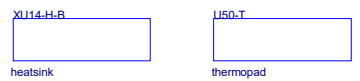
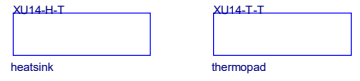
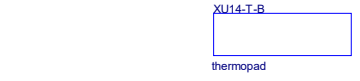
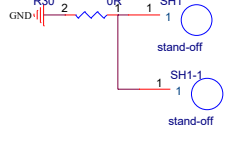
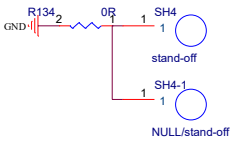
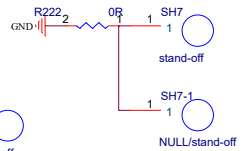
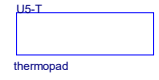
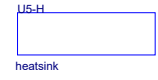
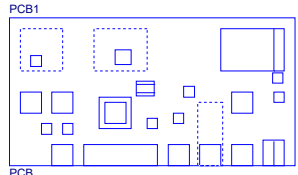
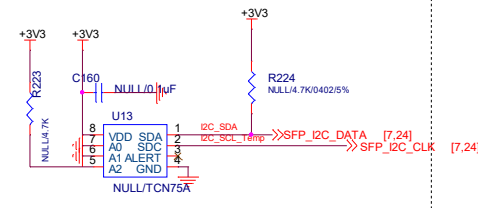
1.1V for VRX518, VRX619



$V_{out} = 0.8 * (1 + 4.32K/10K) = 1.145V$

U22	MP1471A	RT6253B
R285	118K	0R
R284	4.32K	13K
R281	10K	27K
Vref	0.8V	0.765V
Vout	1.145V	1.133V

Temp sensor I2C Addr:1001100



cOrgName> DrayTek		
File	POWER2	
Size	Document Number	Rev
Custom	V2766AX	6B
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REVISION HISTORY

Version	Date	List of Modification	Page
	2020-12-01		Ian
V0A	2020-12-10	2.4GHz FEM (152-5331900-00G,SKY85331-11) : 1. Add XU31, XU33 2. Remove XC12, XC13, XC10, XC11 3. Null XR101, XR88, XU30, XU32 4. Place XR137, XR136 5. Remove XR146, XR149, XR142, XR145 5GHz FEM (152-5743900-00G,SKY85743-31) : 1. Add XU51, XU53 for co-layout with XU52, XU54 2. Remove XR117, XR113, XC16, XC17 3. Remove XR118, XR129, XC181, XC182 4. Place XR11, XR12 6. Null XU61, XR10, XR135 7. Place XR139, XR140 8. Null XU63, XR138, XR141	mChen
V6B	2021-5-28	1. Change VRX619 circuit 2. Add J9 3. colay internal PHY 4	Ian
V6C	2022-02-24	1.C326,C682,C685 colay C1206	Ian
V6D	2022-07-18	1.Add C766, C767, C691, C768, C769, C692, C770, C771, C693	Ian

BOM Difference

	V2765ax	V2765Vax							
(VD)	V	V							
(V)	NULL	V							
(5)	V	V							
(PD)	NULL	NULL							
(AX)	V	V							
(NPD)	V	V							
(AX_LTE)	NULL	NULL							

<OrgName>		DrayTek	
Title		BOM Difference	
Size	Document Number	Rev	
B	V2766AX	6B	
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